

Methodology Used to Determine SuperSpeed USB 10 Gbps (USB 3.1) – Gen2 Channel and Cable Assembly High Speed Compliance

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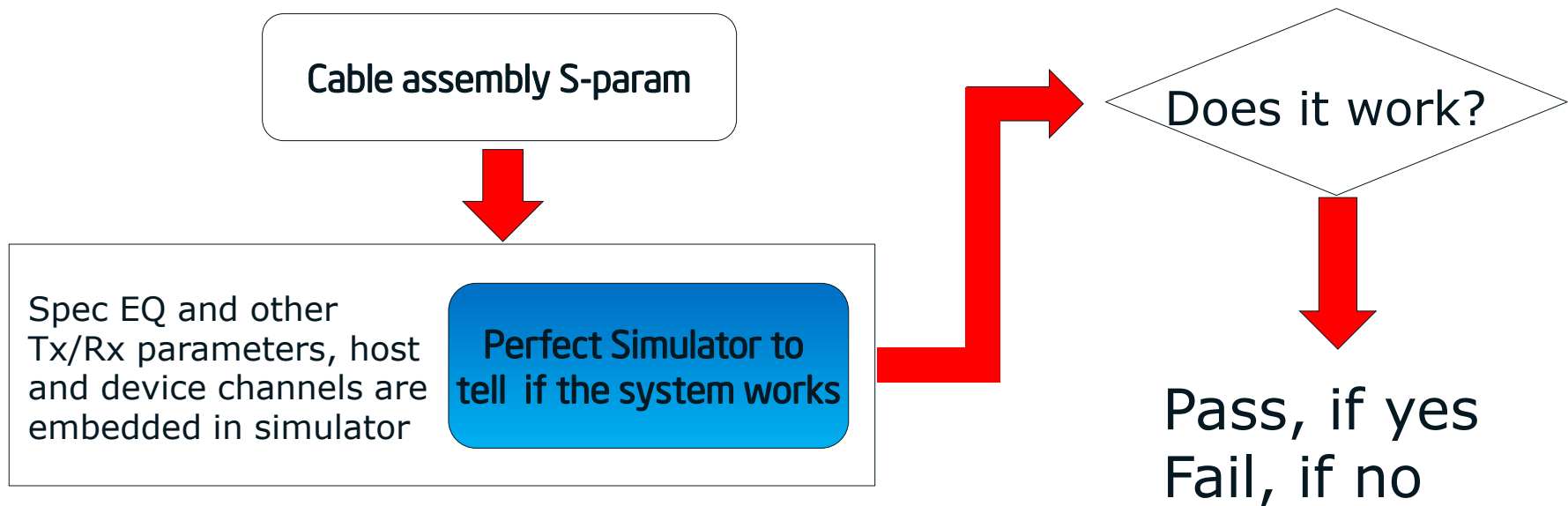
Agenda

- ❑ Objective
- ❑ Channel Electrical Metrics Review
- ❑ Correlation with End-to-End Margin
- ❑ Cable Assembly Spec and Compliance
- ❑ Discussion
- ❑ Summary

Objective

- ❑ *Develop a SuperSpeed USB 10 Gbps (USB 3.1) Gen2 cable assembly compliance specification that directly correlates to the end-to-end link performance/margin.*

In an ideal world ...

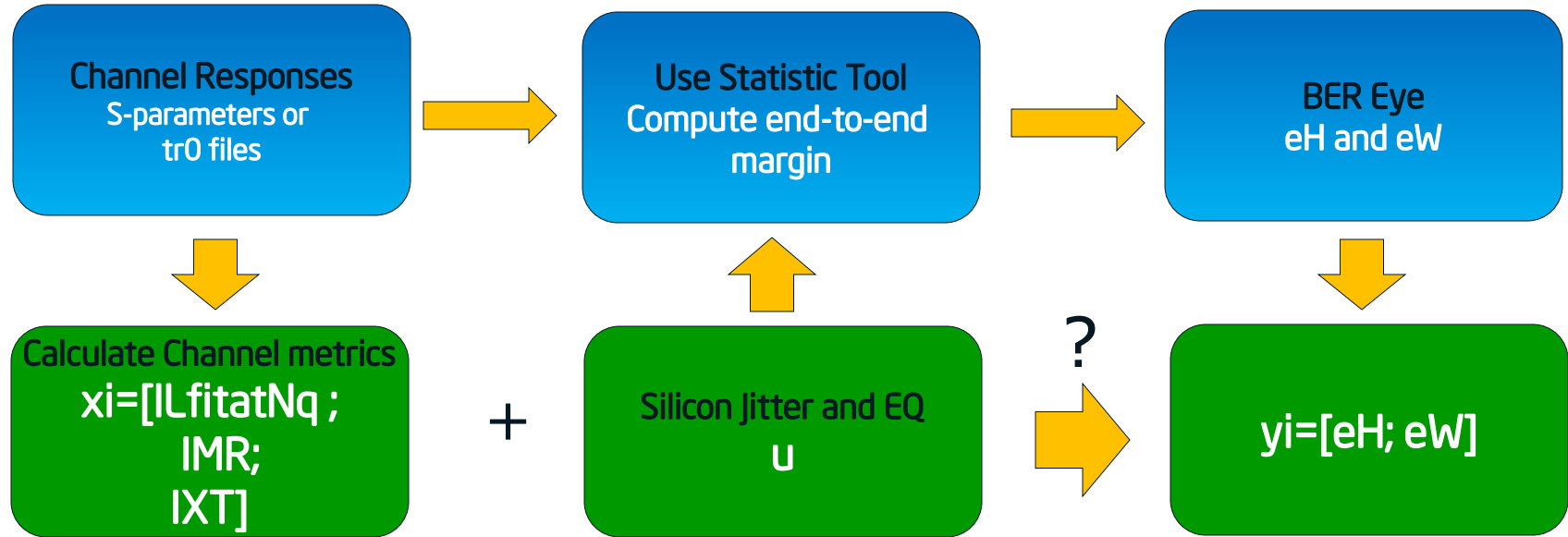


Review of channel metrics

- ❑ The following parameters are used to specify passive channel electrical performance:
 - ❑ Insertion fit at Nyquist frequency (*ILfitatNq*)
 - ❑ Integrated multi-reflection (*IMR*)
 - ❑ Integrated crosstalk (*IXT*)
- ❑ The justification of using those three parameters is based on physical interpretation and *end-to-end correlation*.

See backup

Establishing end-to-end correlation



Establish relationship

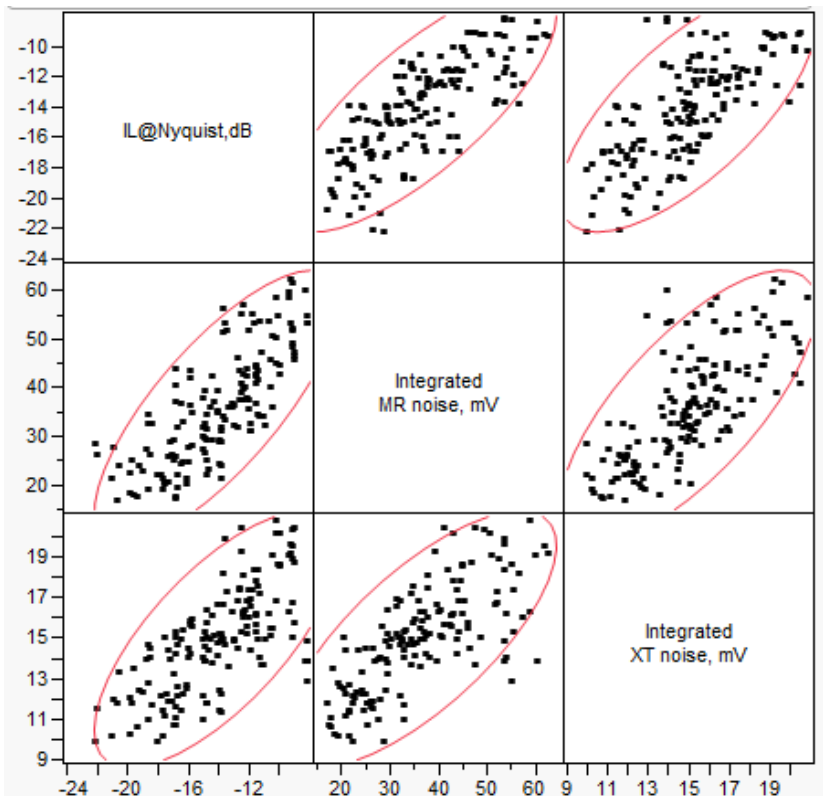
$$y = f(x; u)$$

y=End-to-end margin
f=Prediction function
X=Channel metrics
u=Silicon parameters

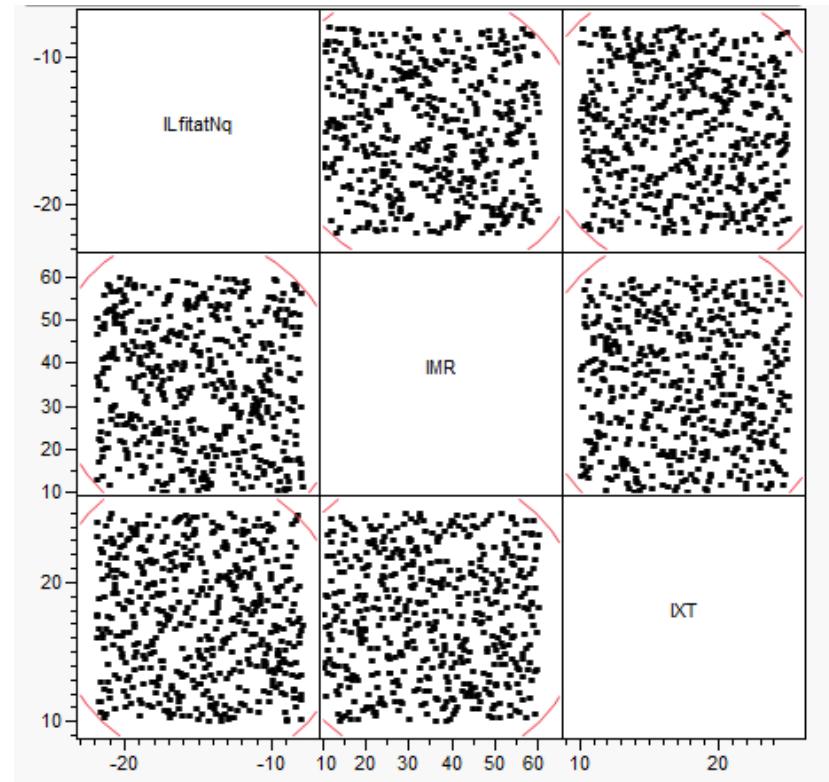
based on input $\{x_i; u\}$ and "observation" $\{y_i\}$, $i=1:n$

Neural network fitting and space filling

- ❑ Powerful tool capable of fitting any smooth function.
- ❑ Important to have sufficient and well-distributed samples.



Not good



Better

Settings for end-to-end simulations

☐ EQ

- Spec reference CTLE's
- 1-tap DFE with a 50 mV max tap value
- De-emphasis with and without pre-cursor tap (separate runs)
 - [-0.1 -0.125] or [0 -0.125].

☐ Buffer

- 800 mV voltage swing (minimum voltage swing)
- Risetime: 0.2UI (0-100%)
- Cpad: 1.1pF (Tx) and 1.0pF (Rx)

☐ Jitter and noise

- Per USB 3.1 spec

☐ Channels

- ~2500 channels with well-distributed and a wide range of ILfitatNq, IMR and IXT

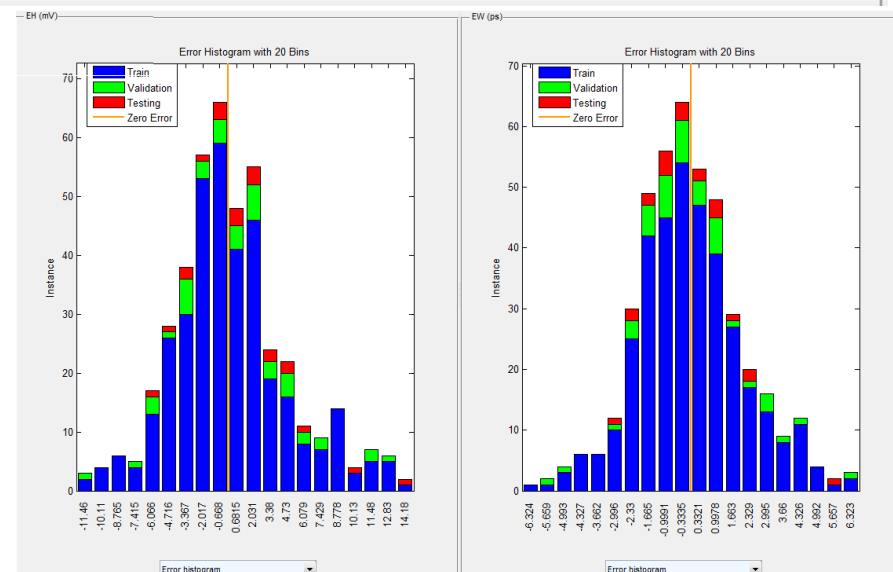
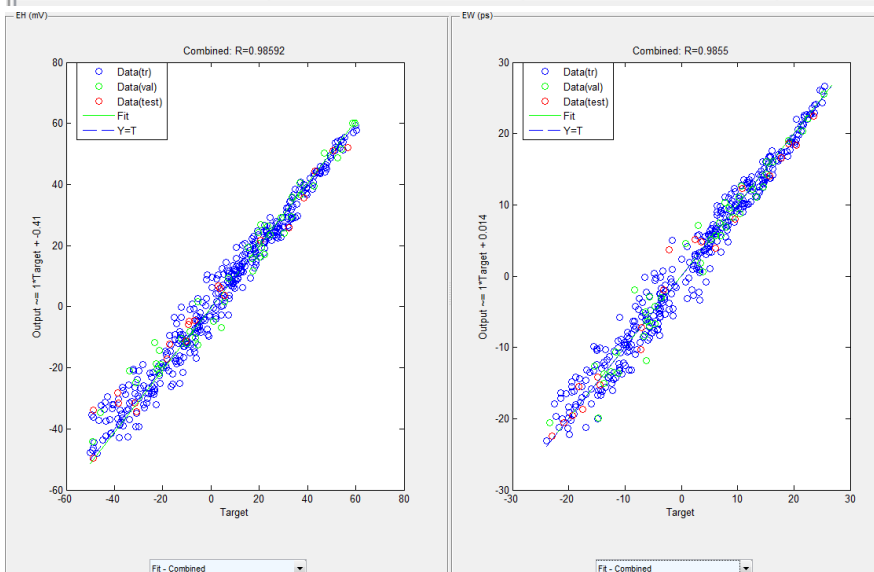
Fitting results

❑ Fitting is reasonably good.

- Typical 95% confidence level: $\sim \pm 10$ mV for eye height and $\sim \pm 5$ ps for eye width
- Further improvement is difficult, but we are still trying

Summary: EH (mV)						
Models	R_train	R_val	R_test	RMSE_train	RMSE_val	RMSE_test
7	0.9858	0.9846	0.9908	4.5390	5.1488	5.0878

Summary: EW (ps)						
Models	R_train	R_val	R_test	RMSE_train	RMSE_val	RMSE_test
7	0.9854	0.9816	0.9913	2.0997	2.2670	1.9791



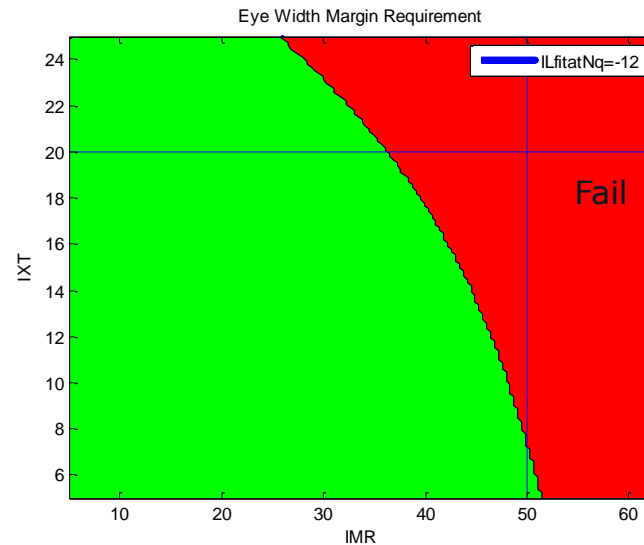
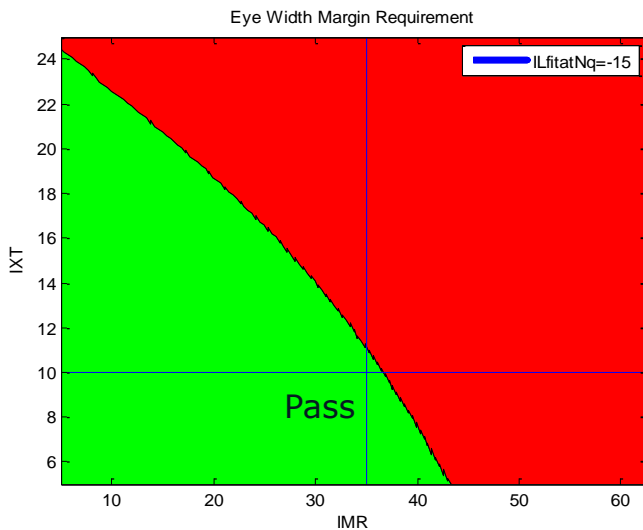
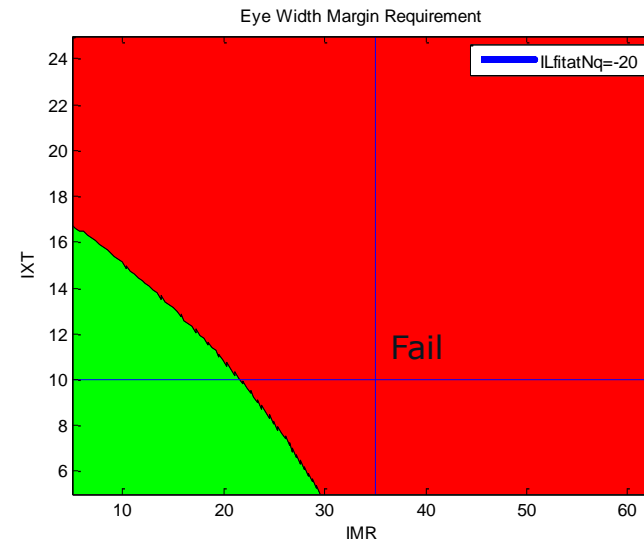
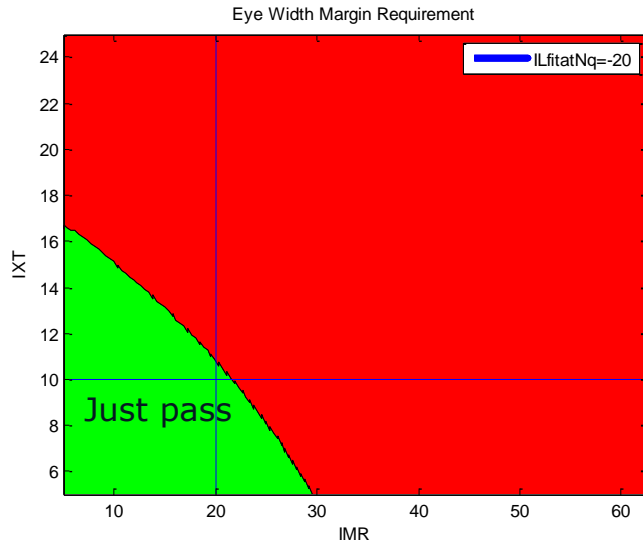
Channel spec

- ❑ The fitting function or prediction formula may be served as the (passive) channel spec:

$$\begin{matrix} \text{ILfitatNq, IMR, IXT} \\ \text{eH} \\ \text{eW} \end{matrix} \quad \mathbf{y=f(\overset{\downarrow}{x})>\text{threshold}}$$

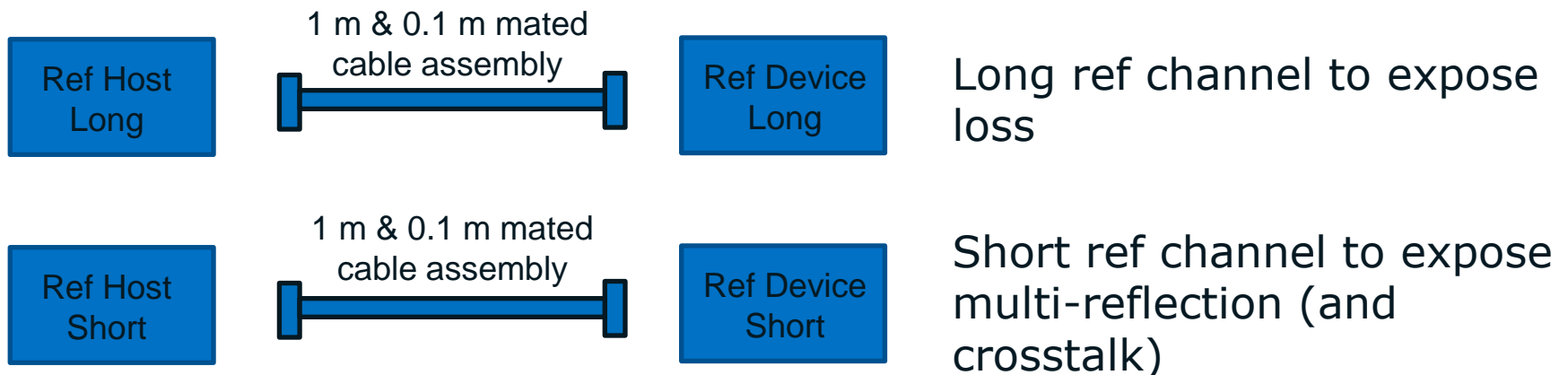
- ❑ The threshold usually is zero. But we may need some guard-band (for fitting error and other factors), for example, a 5 ps threshold for eye width.
- ❑ We choose either eye height or eye width as the pass/fail criterion
 - eH and eW are correlated
 - The choice may depend on fitting quality

A few pass/fail examples



Reference hosts and devices

- ❑ Cable assembly S-param shall be combined with ref host and device to form a full channel.
 - Reference host and device may be viewed as the test fixture for cable assembly.
- ❑ Ref hosts/devices shall somewhat represent the “worst-case” hosts/devices.
- ❑ A cable assembly shall pass with both “long” host/device and “short” host/device



Long reference channel results

- BCss stands for USB 3.1 Gen1 (5 Gbps) Std-A to Std-B mated cable assembly.
- Cable length swept from 10 cm to 100 cm.
- Cable impedance is 100 ohms.
- The pass/fail criterion set by prediction is $eW < 2$ ps.
- *Gen1 connectors need improvement and the cable assembly compliance test must weed them out.*

Cable Assembly	ILfitatNq	IMR, mV	IXT, mV	eH, mV	eW, ps	Prediction
Long_BCss_10cm.mat	-15.9	30.3	18.4	-6	-3	Fail
Long_BCss_14cm.mat	-16.1	29.6	18.1	-7	-4	Fail
Long_BCss_18cm.mat	-16.3	29.2	18.0	-8	-4	Fail
Long_BCss_22cm.mat	-16.5	28.7	17.3	-5	-4	Fail
Long_BCss_28cm.mat	-16.7	27.7	17.2	-6	-4	Fail
Long_BCss_32cm.mat	-16.9	27.2	16.6	-2	-1	Fail
Long_BCss_36cm.mat	-17.1	26.6	16.5	-4	-2	Fail
Long_BCss_40cm.mat	-17.3	26.0	15.9	-9	-5	Fail
Long_BCss_44cm.mat	-17.4	25.6	15.6	-9	-6	Fail
Long_BCss_48cm.mat	-17.6	25.1	15.5	-9	-5	Fail
Long_BCss_52cm.mat	-17.8	24.6	15.1	-7	-5	Fail
Long_BCss_56cm.mat	-18.0	24.2	14.8	-7	-4	Fail
Long_BCss_60cm.mat	-18.1	23.9	14.7	-5	-3	Fail
Long_BCss_64cm.mat	-18.4	23.4	14.3	-5	-3	Fail
Long_BCss_68cm.mat	-18.6	22.9	14.0	-5	-3	Fail
Long_BCss_72cm.mat	-18.9	22.4	13.7	-11	-6	Fail
Long_BCss_76cm.mat	-19.2	21.8	13.3	-11	-6	Fail
Long_BCss_80cm.mat	-19.4	21.3	13.0	-8	-5	Fail
Long_BCss_84cm.mat	-19.7	20.9	12.8	-7	-5	Fail
Long_BCss_88cm.mat	-20.0	20.5	12.5	-6	-4	Fail
Long_BCss_92cm.mat	-20.2	20.1	12.2	-5	-3	Fail
Long_BCss_96cm.mat	-20.5	19.7	12.0	-12	-6	Fail
Long_BCss_100cm.mat	-20.8	19.3	11.8	-9	-4	Fail

Long reference channel results, cont.

- BCsm stands for USB 3.1 Gen1 (5 Gbps) Std-A to Micro-B mated cable assembly.
- Cable length swept from 10 cm to 100 cm.
- Cable impedance is 100 ohms.
- The pass/fail criterion set by prediction is $eW < 2$ ps.
- Gen1 connectors need improvement.

Cable Assembly	ILfitatNq	IMR, mV	IXT, mV	eH, mV	eW, ps	Prediction
Long_BCsm_10cm_100ohm	-15.7	31.9	16.7	-5	-4	Fail
Long_BCsm_14cm_100ohm	-15.8	30.9	16.6	-1	-1	Fail
Long_BCsm_18cm_100ohm	-16.0	30.1	16.3	0	0	Fail
Long_BCsm_22cm_100ohm	-16.2	29.3	16.0	2	2	Fail
Long_BCsm_28cm_100ohm	-16.5	28.6	15.7	-1	-1	Fail
Long_BCsm_32cm_100ohm	-16.6	27.9	15.5	3	3	Fail
Long_BCsm_36cm_100ohm	-16.8	27.4	15.3	1	1	Fail
Long_BCsm_40cm_100ohm	-17.0	26.9	15.1	2	1	Fail
Long_BCsm_44cm_100ohm	-17.2	26.4	14.9	3	2	Fail
Long_BCsm_48cm_100ohm	-17.4	25.9	14.7	3	3	Pass
Long_BCsm_52cm_100ohm	-17.5	25.5	14.5	2	2	Pass
Long_BCsm_56cm_100ohm	-17.7	25.1	14.4	-2	-2	Fail
Long_BCsm_60cm_100ohm	-17.9	24.6	14.2	4	2	Fail
Long_BCsm_64cm_100ohm	-18.1	24.1	14.1	-2	-2	Fail
Long_BCsm_68cm_100ohm	-18.2	23.7	13.9	2	2	Pass
Long_BCsm_72cm_100ohm	-18.5	23.3	13.7	-1	-1	Fail
Long_BCsm_76cm_100ohm	-18.7	22.8	13.5	1	1	Fail
Long_BCsm_80cm_100ohm	-19.0	22.2	13.3	-1	-2	Fail
Long_BCsm_84cm_100ohm	-19.3	21.7	13.1	2	1	Fail
Long_BCsm_88cm_100ohm	-19.5	21.2	13.0	-3	-3	Fail
Long_BCsm_92cm_100ohm	-19.8	20.8	12.8	-2	-1	Fail
Long_BCsm_96cm_100ohm	-20.1	20.4	12.6	-3	-2	Fail
Long_BCsm_100cm_100ohm	-20.3	19.9	12.5	-1	-1	Fail

Long reference channel results, cont.

- BCsm stands for USB 3.1 Gen1 (5 Gbps) Std-A to Micro-B mated cable assembly.
- Cable length swept from 10 cm to 100 cm.
- Cable impedance is 80 ohms.
- Lower cable impedance has less reflection, so more opened eye.
- The pass/fail criterion set by prediction is $eW < 2$ ps.

Cable Assembly	ILfitatNq	IMR, mV	IXT, mV	eH, mV	eW, ps	Prediction
Long_BCsm_10cm.mat	-15.6	27.1	17.3	7	4	Pass
Long_BCsm_14cm.mat	-15.8	28.0	17.2	5	3	Pass
Long_BCsm_18cm.mat	-16.0	27.1	16.9	4	3	Pass
Long_BCsm_22cm.mat	-16.2	26.4	16.6	4	3	Pass
Long_BCsm_28cm.mat	-16.4	25.6	16.3	4	3	Pass
Long_BCsm_32cm.mat	-16.6	24.9	16.1	5	3	Pass
Long_BCsm_36cm.mat	-16.8	24.4	15.8	5	3	Pass
Long_BCsm_40cm.mat	-17.0	24.0	15.6	7	4	Pass
Long_BCsm_44cm.mat	-17.2	23.5	15.4	6	5	Pass
Long_BCsm_48cm.mat	-17.3	23.0	15.2	5	4	Pass
Long_BCsm_52cm.mat	-17.5	22.5	15.0	6	4	Pass
Long_BCsm_56cm.mat	-17.7	22.1	14.8	3	2	Pass
Long_BCsm_60cm.mat	-18.1	21.6	14.7	3	2	Pass
Long_BCsm_64cm.mat	-18.3	21.1	14.5	3	2	Pass
Long_BCsm_68cm.mat	-18.5	20.7	14.4	4	3	Pass
Long_BCsm_72cm.mat	-18.7	20.3	14.2	5	3	Pass
Long_BCsm_76cm.mat	-19.0	19.7	13.9	6	3	Pass
Long_BCsm_80cm.mat	-19.3	19.1	13.7	4	3	Pass
Long_BCsm_84cm.mat	-19.5	18.7	13.5	1	2	Pass
Long_BCsm_88cm.mat	-19.8	18.2	13.3	3	2	Pass
Long_BCsm_92cm.mat	-20.1	17.7	13.2	2	2	Pass
Long_BCsm_96cm.mat	-20.3	17.4	13.0	2	2	Pass
Long_BCsm_100cm.mat	-20.6	16.9	12.8	3	2	Pass

80 ohm cable is better than 100 ohm cable

Long reference channel results, cont.

- Chs stands for USB 3.1 Gen2 (10 Gbps) Std-A to Std-B mated cable assembly.
- Cable length swept from 10 cm to 100 cm.
- Cable impedance is 100 ohms.
- The pass/fail criterion set by prediction is $eW < 2$ ps.
- Gen2 connectors have some improvement but the margin is still at the borderline.

Cable Assembly	ILfitatNq	IMR, mV	IXT, mV	eH, mV	eW, ps	Prediction
Long_ChS_10cm.mat	-15.7	34.7	15.9	4	2	Fail
Long_ChS_14cm.mat	-15.9	33.3	16.2	4	3	Fail
Long_ChS_18cm.mat	-16.1	32.6	16.4	0	0	Fail
Long_ChS_22cm.mat	-16.2	32.2	16.1	-1	-1	Fail
Long_ChS_28cm.mat	-16.5	31.1	15.3	-1	-1	Fail
Long_ChS_32cm.mat	-16.7	30.5	14.9	1	1	Fail
Long_ChS_36cm.mat	-16.9	29.9	14.8	1	1	Fail
Long_ChS_40cm.mat	-17.0	29.3	14.4	2	1	Fail
Long_ChS_44cm.mat	-17.2	28.8	13.9	2	1	Fail
Long_ChS_48cm.mat	-17.4	28.3	13.8	2	2	Fail
Long_ChS_52cm.mat	-17.6	27.8	13.5	1	1	Fail
Long_ChS_56cm.mat	-17.8	27.3	13.2	0	0	Fail
Long_ChS_60cm.mat	-17.9	26.9	13.0	3	2	Fail
Long_ChS_64cm.mat	-18.2	26.3	12.7	2	2	Pass
Long_ChS_68cm.mat	-18.4	25.7	12.3	1	2	Pass
Long_ChS_72cm.mat	-18.7	25.1	12.0	2	2	Pass
Long_ChS_76cm.mat	-19.0	24.5	11.7	2	2	Pass
Long_ChS_80cm.mat	-19.2	23.9	11.4	-3	-2	Pass
Long_ChS_84cm.mat	-19.5	23.4	11.1	-2	-2	Pass
Long_ChS_88cm.mat	-19.8	22.9	10.8	-1	-1	Pass
Long_ChS_92cm.mat	-20.0	22.5	10.6	1	1	Pass
Long_ChS_96cm.mat	-20.3	22.0	10.3	1	1	Pass
Long_ChS_100cm.mat	-20.6	21.5	10.1	3	2	Pass

Long reference channel results, cont.

- Csm stands for USB 3.1 Gen2 (10 Gbps) Std-A to Micro-B mated cable assembly.
- Cable length swept from 10 cm to 100 cm.
- Cable impedance is 100 ohms.
- The pass/fail criterion set by prediction is $eW < 2$ ps.
- Gen2 connectors have some improvement and the timing margin is decent.

Cable Assembly	ILfitatNq	IMR, mV	IXT, mV	eH, mV	eW, ps	Prediction
Long_Csm_v2_10cm_100ohn	-15.8	33.3	14.6	7	4	Pass
Long_Csm_v2_14cm_100ohn	-16.0	31.7	14.6	12	6	Pass
Long_Csm_v2_18cm_100ohn	-16.1	30.8	14.0	9	5	Pass
Long_Csm_v2_22cm_100ohn	-16.3	30.1	13.8	12	6	Pass
Long_Csm_v2_28cm_100ohn	-16.6	29.2	13.2	12	6	Pass
Long_Csm_v2_32cm_100ohn	-16.8	28.6	13.0	10	5	Pass
Long_Csm_v2_36cm_100ohn	-16.9	28.0	12.7	10	5	Pass
Long_Csm_v2_40cm_100ohn	-17.1	27.5	12.3	11	6	Pass
Long_Csm_v2_44cm_100ohn	-17.3	27.0	12.0	11	6	Pass
Long_Csm_v2_48cm_100ohn	-17.5	26.6	11.8	12	6	Pass
Long_Csm_v2_52cm_100ohn	-17.7	26.1	11.5	14	6	Pass
Long_Csm_v2_56cm_100ohn	-17.8	25.6	11.3	13	6	Pass
Long_Csm_v2_60cm_100ohn	-18.0	25.2	11.0	13	6	Pass
Long_Csm_v2_64cm_100ohn	-18.2	24.8	10.8	12	6	Pass
Long_Csm_v2_68cm_100ohn	-18.4	24.4	10.6	11	6	Pass
Long_Csm_v2_72cm_100ohn	-18.6	23.9	10.3	12	7	Pass
Long_Csm_v2_76cm_100ohn	-18.9	23.3	10.0	12	7	Pass
Long_Csm_v2_80cm_100ohn	-19.1	22.8	9.7	14	7	Pass
Long_Csm_v2_84cm_100ohn	-19.4	22.3	9.5	10	5	Pass
Long_Csm_v2_88cm_100ohn	-19.7	21.8	9.2	14	7	Pass
Long_Csm_v2_92cm_100ohn	-19.9	21.3	9.0	12	6	Pass
Long_Csm_v2_96cm_100ohn	-20.2	20.9	8.8	10	5	Pass
Long_Csm_v2_100cm_100oh	-20.5	20.5	8.5	11	6	Pass

Long reference channel results, cont.

- Csm stands for USB 3.1 Gen2 (10 Gbps) Std-A to Micro-B mated cable assembly.
- Cable length swept from 10 cm to 100 cm.
- Cable impedance is 80 ohms.
- The pass/fail criterion set by prediction is $eW < 2$ ps.
- Gen2 connectors have some improvement and the timing margin is decent.

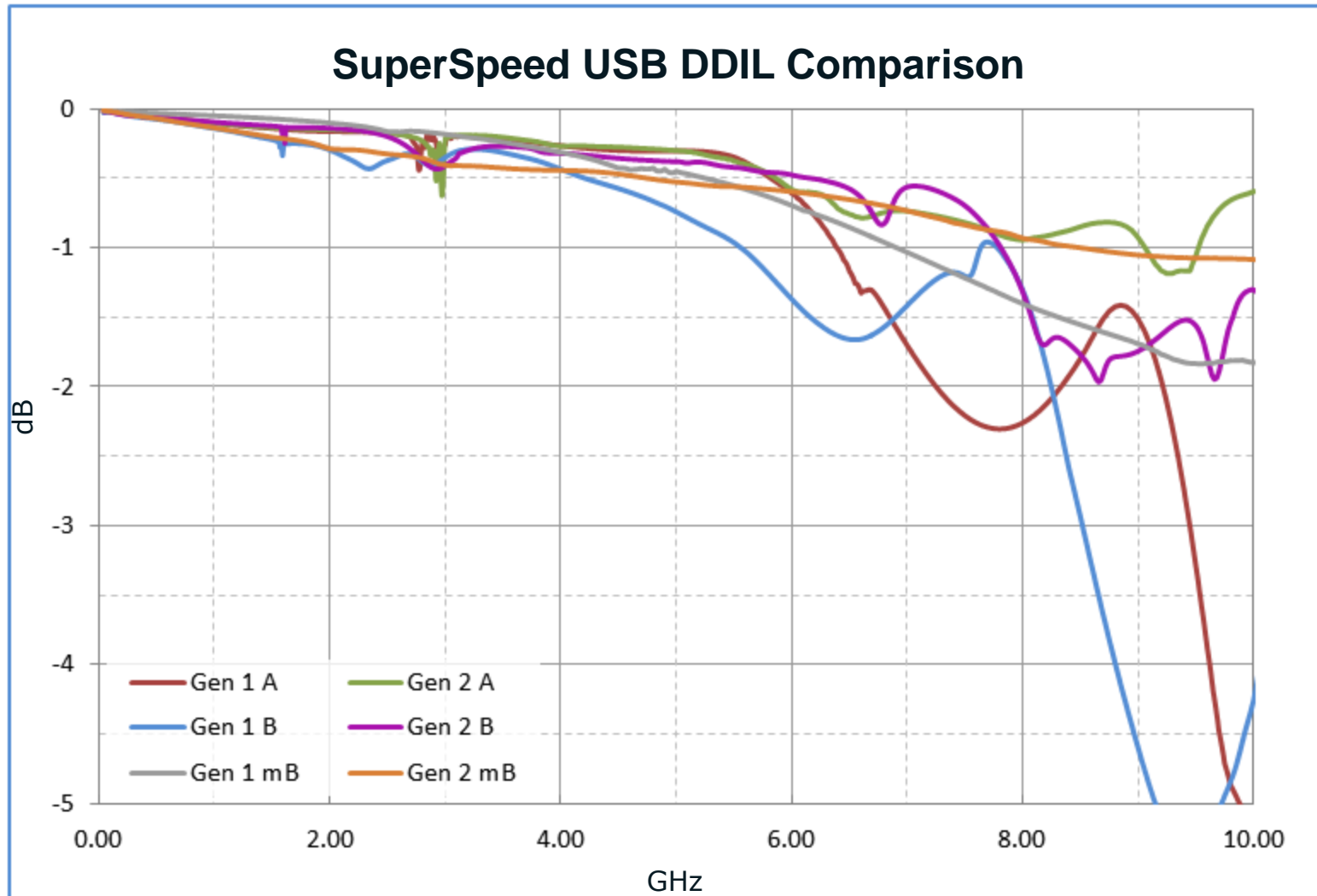
Cable Assembly	ILfitatNq	IMR, mV	IXT, mV	eH, mV	eW, ps	Prediction
Long_Csm_v2_10cm.mat	-15.7	27.8	15.3	16	8	Pass
Long_Csm_v2_14cm.mat	-15.9	27.6	15.2	13	8	Pass
Long_Csm_v2_18cm.mat	-16.1	26.8	14.9	14	8	Pass
Long_Csm_v2_22cm.mat	-16.3	26.1	14.6	14	8	Pass
Long_Csm_v2_28cm.mat	-16.5	25.3	14.1	14	7	Pass
Long_Csm_v2_32cm.mat	-16.7	24.7	13.8	13	7	Pass
Long_Csm_v2_36cm.mat	-16.9	24.1	13.4	16	8	Pass
Long_Csm_v2_40cm.mat	-17.1	23.6	13.1	17	8	Pass
Long_Csm_v2_44cm.mat	-17.3	23.1	12.8	16	8	Pass
Long_Csm_v2_48cm.mat	-17.4	22.7	12.6	12	7	Pass
Long_Csm_v2_52cm.mat	-17.6	22.2	12.3	16	8	Pass
Long_Csm_v2_56cm.mat	-17.8	21.8	12.1	17	9	Pass
Long_Csm_v2_60cm.mat	-18.0	21.4	11.8	15	7	Pass
Long_Csm_v2_64cm.mat	-18.2	20.9	11.6	16	9	Pass
Long_Csm_v2_68cm.mat	-18.3	20.6	11.4	16	9	Pass
Long_Csm_v2_72cm.mat	-18.9	20.1	11.1	17	8	Pass
Long_Csm_v2_76cm.mat	-19.2	19.5	10.8	18	9	Pass
Long_Csm_v2_80cm.mat	-19.5	19.0	10.5	18	9	Pass
Long_Csm_v2_84cm.mat	-19.7	18.5	10.2	19	10	Pass
Long_Csm_v2_88cm.mat	-20.0	18.0	10.0	20	10	Pass
Long_Csm_v2_92cm.mat	-20.3	17.5	9.8	21	10	Pass
Long_Csm_v2_96cm.mat	-20.5	17.1	9.5	21	10	Pass
Long_Csm_v2_100cm.mat	-20.8	16.7	9.3	21	10	Pass

Short reference channel results

- Csm stands for USB 3.1 Gen2 (10 Gbps) Std-A to Micro-B mated cable assembly.
- Cable length swept from 10 cm to 100 cm.
- Cable impedance is 80 ohms.
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- Gen2 connectors have some improvement and the timing margin is decent.

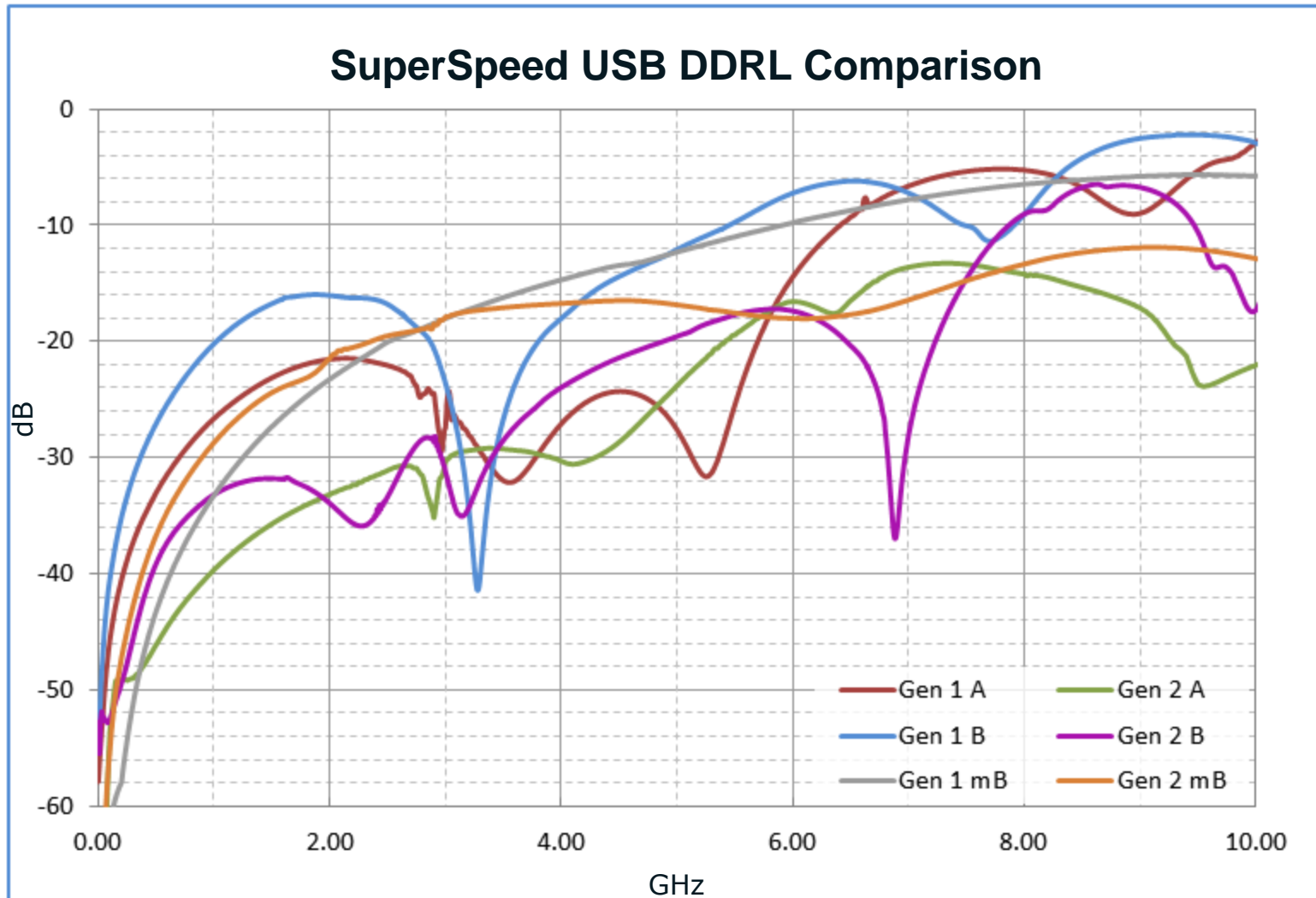
Cable Assembly	ILfitatNq	IMR, mV	IXT, mV	eH, mV	eW, ps	Prediction
Short_Csm_v2_10cm.mat	-10.3	48.7	17.7	21	11	Pass
Short_Csm_v2_14cm.mat	-10.5	47.5	17.4	22	12	Pass
Short_Csm_v2_18cm.mat	-10.7	46.4	17.0	21	12	Pass
Short_Csm_v2_22cm.mat	-10.8	45.3	16.8	19	11	Pass
Short_Csm_v2_28cm.mat	-11.1	43.7	16.1	18	11	Pass
Short_Csm_v2_32cm.mat	-11.3	42.8	15.7	16	10	Pass
Short_Csm_v2_36cm.mat	-11.5	41.9	15.4	22	12	Pass
Short_Csm_v2_40cm.mat	-11.6	41.0	15.0	23	12	Pass
Short_Csm_v2_44cm.mat	-11.8	40.2	14.7	21	12	Pass
Short_Csm_v2_48cm.mat	-12.0	39.4	14.4	22	12	Pass
Short_Csm_v2_52cm.mat	-12.2	38.7	14.1	20	12	Pass
Short_Csm_v2_56cm.mat	-12.4	38.0	13.8	23	12	Pass
Short_Csm_v2_60cm.mat	-12.5	37.2	13.6	24	13	Pass
Short_Csm_v2_64cm.mat	-12.7	36.6	13.3	25	13	Pass
Short_Csm_v2_68cm.mat	-12.9	35.9	13.1	27	12	Pass
Short_Csm_v2_72cm.mat	-13.1	35.2	12.8	25	12	Pass
Short_Csm_v2_76cm.mat	-13.4	34.3	12.5	24	12	Pass
Short_Csm_v2_80cm.mat	-13.6	33.4	12.2	26	13	Pass
Short_Csm_v2_84cm.mat	-13.9	32.6	12.0	24	13	Pass
Short_Csm_v2_88cm.mat	-14.1	31.9	11.7	24	12	Pass
Short_Csm_v2_92cm.mat	-14.4	31.0	11.5	20	12	Pass
Short_Csm_v2_96cm.mat	-14.7	30.3	11.2	25	13	Pass
Short_Csm_v2_100cm.ma	-14.9	29.7	11.0	24	12	Pass

Connector Frequency Response



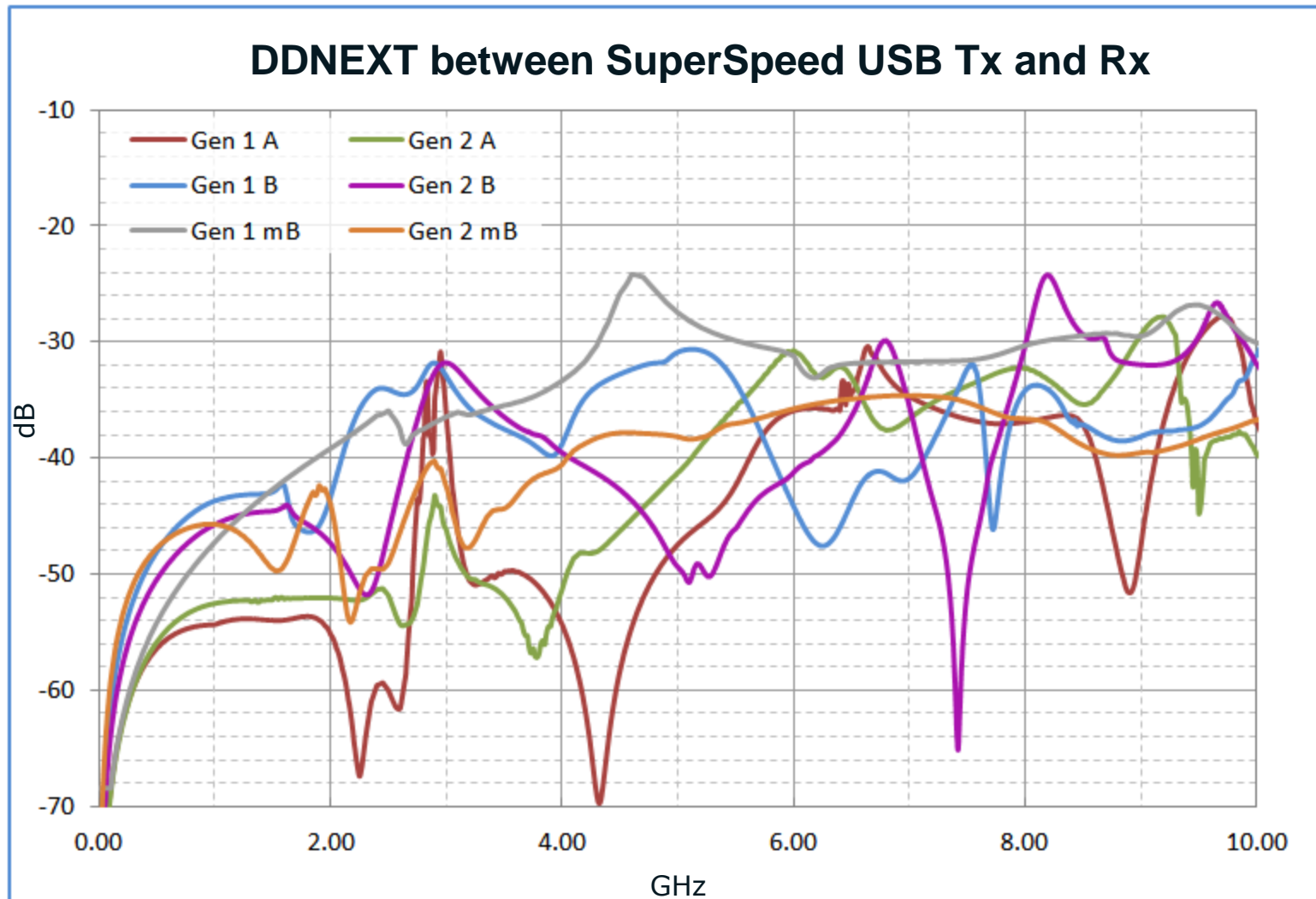
USB 3.1 Gen1 (5 Gbps); Gen2 (10 Gbps)

Connector Frequency Response, cont.



USB 3.1 Gen1 (5 Gbps); Gen2 (10 Gbps)

Connector Frequency Response, cont.



USB 3.1 Gen1 (5 Gbps); Gen2 (10 Gbps)

Observation and discussion

- ❑ Not much margin overall.
 - Options to improve margin:
 - Reference host/device with better performance
 - Better EQ capabilities
 - Tighter Si parameters
- ❑ The margin prediction function does its job.
 - Majority of failure cases are caught and some borderline passing cases are predicted “failing” – looking for further fitting accuracy improvement.
- ❑ The Gen 1 connectors need improvement, as expected.
 - Gen 2 Std-A to Gen 2 Micro-B cable has the best margin.
- ❑ The 80-ohm cable gives better margin than 100-ohm cable
 - Assume they have the same loss.

Cable assembly spec

- ❑ Informative – design targets or guidelines; traditional approach.
 - Mated impedance / return loss
 - Insertion loss
 - Crosstalk
- ❑ Normative – pass/fail, compliance criteria
 - Using the prediction function derived from neural network fitting, say, $eW = f(ILfitatNq, IMR, IXT) > eWmin$.
 - Spec should include definitions of
 - ILfitatNq, IMR an IXT
 - Reference hosts and devices
 - Standard test fixtures (requirements)
 - Other parameters
 - Mode conversion (SCD21)
 - Other EMC requirements

Summary

- ❑ Traditionally, (passive) channel electrical spec defines separate hard limits for insertion loss, return loss and crosstalk over certain frequency range.
- ❑ The shortcomings of such a methodology are:
 - ❑ Specifying limits over a frequency range is challenging and violating the limits at any frequency will fail the spec. But in reality, such channels may work just fine.
 - ❑ It does not allow tradeoffs among insertion loss, return loss and crosstalk.
 - ❑ Channels with less crosstalk or reflection may allow more insertion loss.
 - ❑ Channel with less loss can tolerate more crosstalk or reflection.

Summary

- ❑ A new approach is proposed for cable assembly compliance, using three simple parameters $IL_{fitatNq}$, IMR and IXT.
- ❑ The compliance criterion is directly related to the end-to-end link performance (BER eye margin).
 - ❑ Reasonably good fit was achieved.
- ❑ The new spec allows tradeoffs among loss, reflection and crosstalk.
- ❑ Continued improvement needed
 - ❑ Fitting accuracy
 - ❑ Reference hosts/devices
 - ❑ Connector designs
 - ❑ Si parameters

Backups

Introducing Channel Electrical Metrics

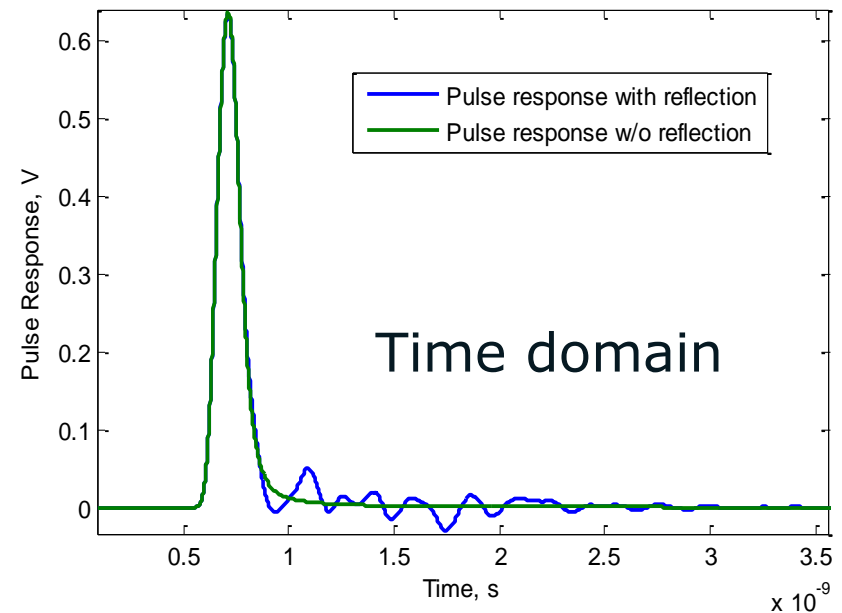
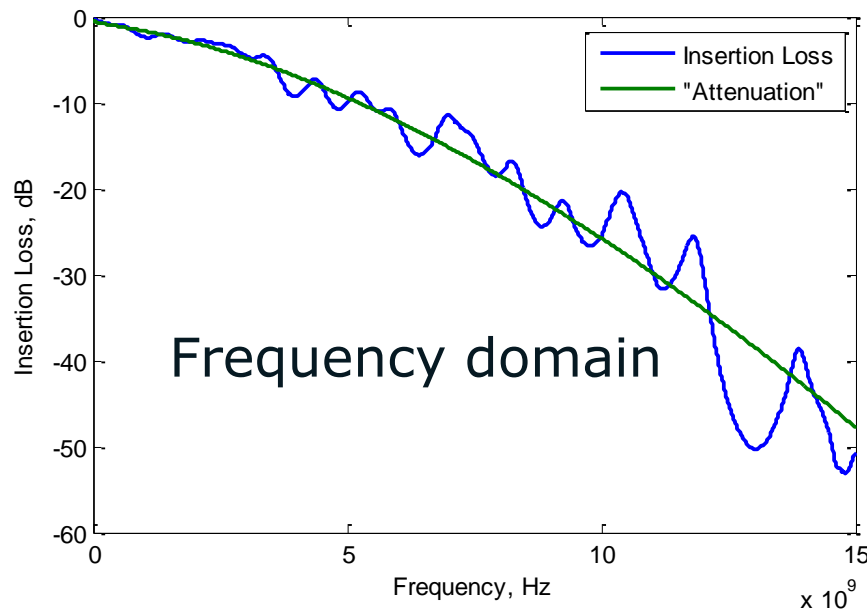
Start with Defining Channel Electrical Metrics

Signal Integrity Impairments

- ❑ There are three impairments that impact channel signal integrity:
 - ❑ Attenuation
 - ❑ Reflection
 - ❑ Crosstalk
- ❑ Passive channel electrical spec is all about managing those three signal integrity impairments.
- ❑ What are the appropriate metrics to describe those three impairments?

Channel Insertion Loss

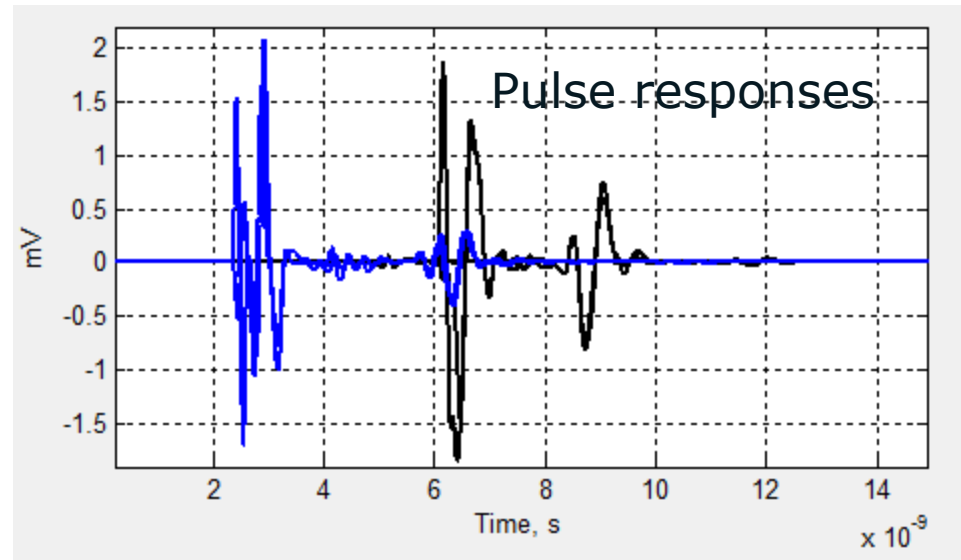
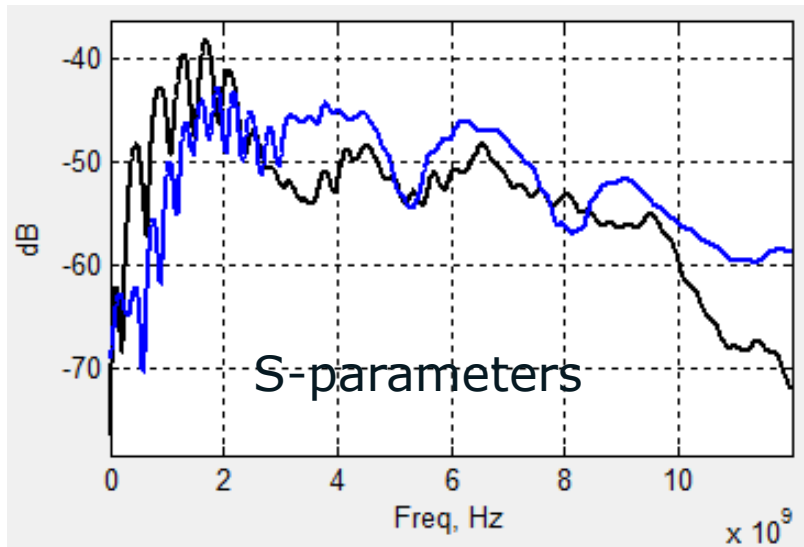
- ❑ The effect of attenuation and (multi) reflection is included in channel insertion loss.



- The smooth curve represents "attenuation" without multi-reflection.
- The ripples represent multi-reflection.

Channel Crosstalk

- ❑ Channel crosstalk can be described in frequency (S-parameter) or time domain (pulse response) also.
- ❑ Power sum is commonly used to combine multiple crosstalks into one.



Appropriate Channel Metrics

- ❑ The appropriate (passive) channel metrics should have the following characteristics:
 - ❑ Correlate to the channel end-to-end electrical performance.
 - ❑ Represent the three channel signal integrity impairments.
 - ❑ Are simple scalar parameters, not the whole frequency or time responses or profiles.
 - ❑ Can be easily and consistently derived from the channel frequency or time domain responses.

Learn from Backplane Community

- ❑ The backplane community has have been using the following parameters to specify passive channel electrical performance:
 - ❑ Insertion fit at Nyquist frequency
 - ❑ Integrated multi-reflection
 - ❑ Integrated crosstalk
- ❑ The justification of using those three parameters will be based on physical interpretation and end-to-end correlation.

Details of Channel Electrical Metrics

Obtaining Channel IL from tr0

- Channel IL, or more appropriately, transfer function may come from time or frequency domain.
- Deriving channel IL from time domain response is common at Intel, using a Hspice. The result is a tr0 file or a channel step response.
 - *The Tx buffer strength and risetime, and Tx and Rx terminations are included in the step response.*
- Let $sr(t)$ be the channel step response. The channel impulse response is then simply: **$ir(t) = \text{diff}(sr(t))$** .
- The channel IL is then: **$IL(f) = \text{fft}(ir(t)) / V_{sw}$** , where V_{sw} is the magnitude of the stimulus, inputting to the channel.
 - Dividing with V_{sw} is necessary to be consistent with the IL or transfer function definition – the magnitude of the stimulus impulse to the transfer function should be unit or 1

Obtaining Channel IL from S-parameter

- Channel S-parameters usually does not include Tx and Rx terminations.
- So the first step is to add Tx and Rx termination to the channel S-parameters.
 - This can be done by cascading abcd-matrices (there are other ways to do so also)
 - The resulting abcd parameters can be converted to z-parameter $Z(f)$. The transfer function $IL(f)$ is then

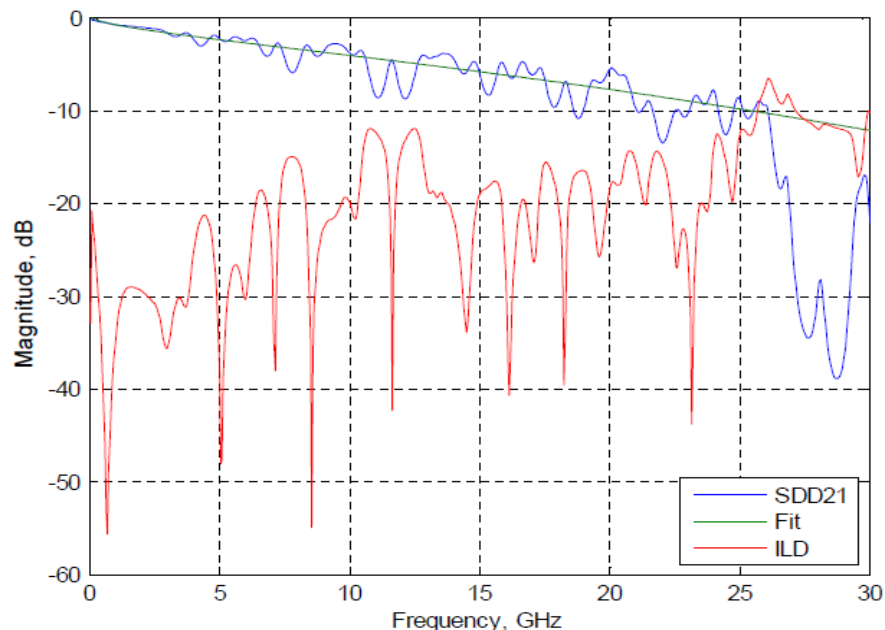
$$V_{rx}(f) = IL(f)V_{in}(f)$$

where

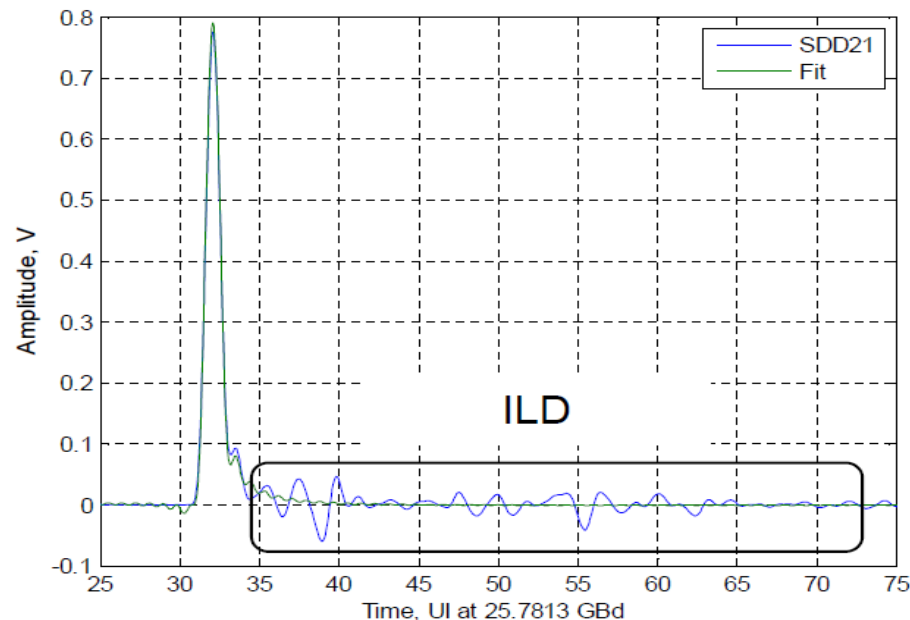
$$IL(f) = \frac{Z(f)}{R_{tx}} \quad Z(f) \text{ is the Z-parameter}$$

Decomposing IL

S-parameter



Pulse response



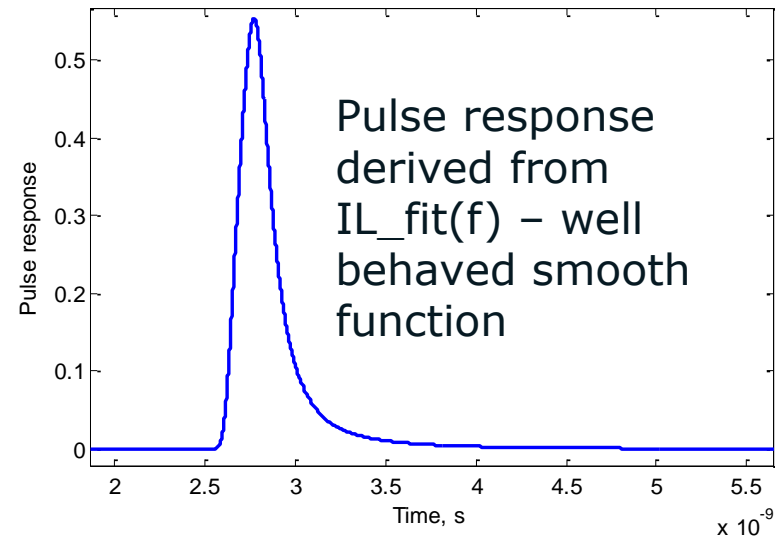
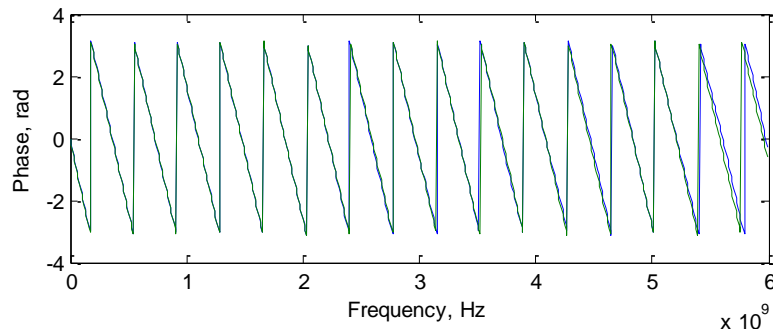
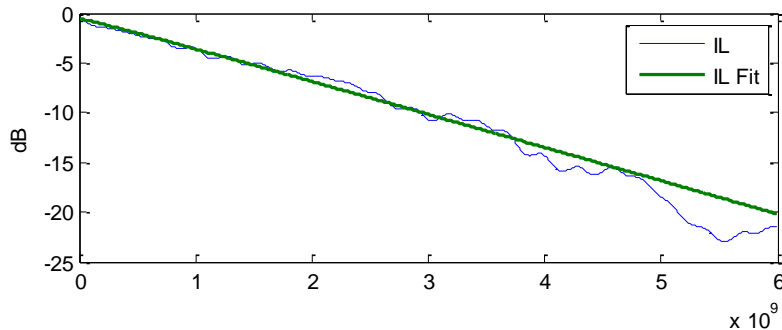
- Insertion loss fit is a smooth function fit of the insertion loss $IL(f)$, representing the *loss without multi-reflection*.
- Insertion loss deviation represents the loss caused by *multi-reflection*.

$$IL(f) = IL_fit(f) + ILD(f)$$

$$ILD(f) = IL(f) - IL_fit(f)$$

Insertion Loss Fit

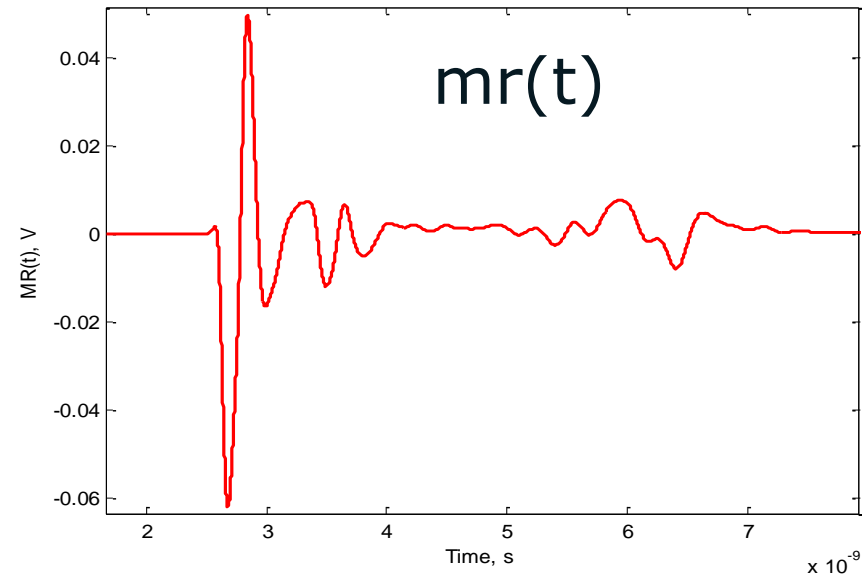
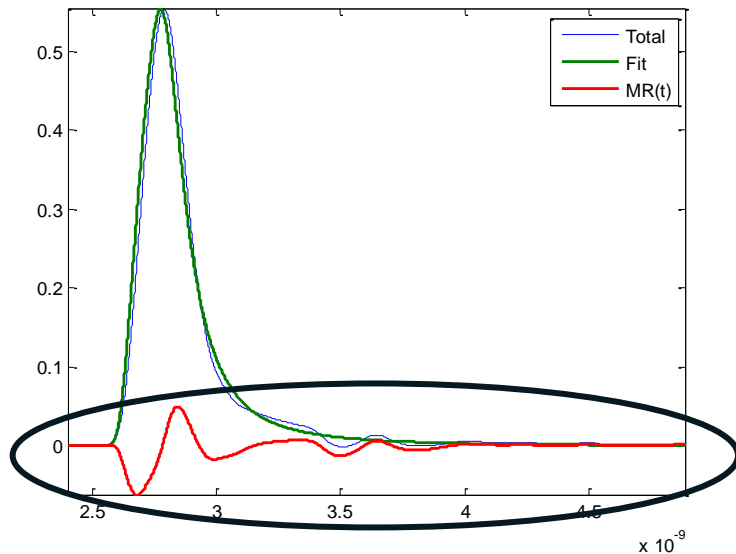
- Use **$IL_fit(f) = \exp(a + b \cdot \sqrt{f} + c \cdot f + d \cdot f^{1.5})$** to fit the insertion loss
 - a – DC loss
 - $b \cdot \sqrt{f}$ – skin effect
 - rest – dielectric loss



IL fit at the Nyquist frequency, $IL_fit(f_0)$, is a good measure of the amplitude and shape of the IL fit pulse response

Multi-reflection

- Multi-reflection noise in frequency domain
 - $\mathbf{MR(f) = V_{in}(f) * ILD(f)}$, where $V_{in}(f)$ is the input pulse spectrum
- Multi-reflection noise in time domain
 - $\mathbf{mr(t) = v_{in}(t) \otimes (ir_{IL}(t) - ir_{fit}(t)) = pr_{IL}(t) - pr_{fit}(t)}$, where ir = impulse response, pr = pulse response



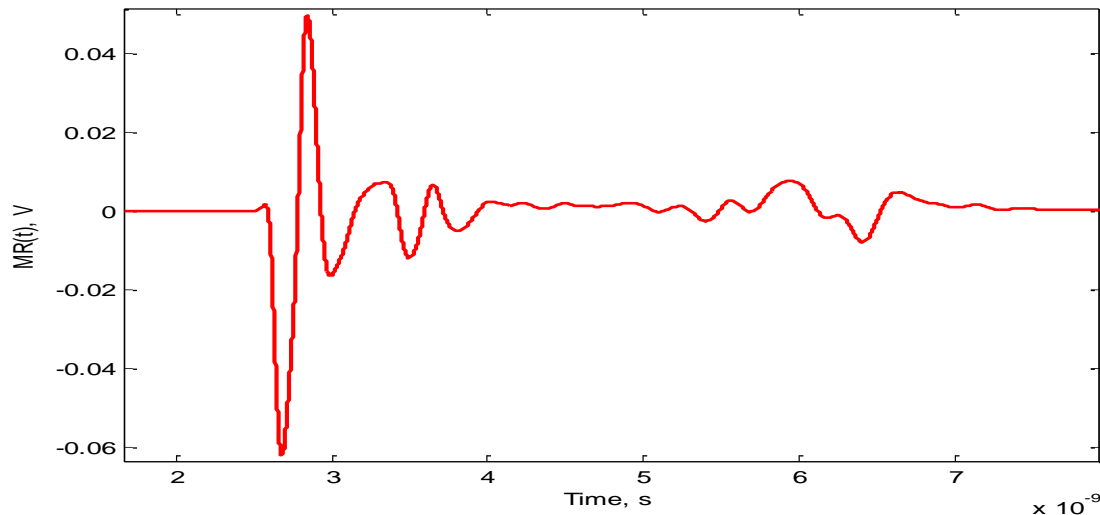
Integrated Multi-reflection

- Power due to multi-reflection is:

$$E_{mr} = \int_{-\infty}^{+\infty} |mr(t)|^2 dt = \int_{-\infty}^{+\infty} |MR(f)|^2 df \quad (\text{Parseval's theorem})$$

- Define the integrated multi-reflection as

$$IMR = V_{sw} \sqrt{\frac{E_{mr}}{E}} \quad \text{in V or mV, normalized with a factor of E}$$



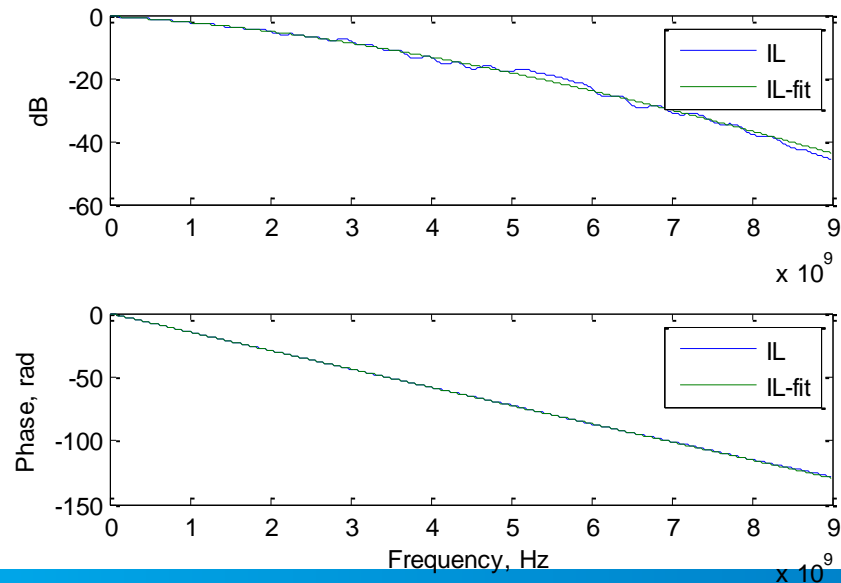
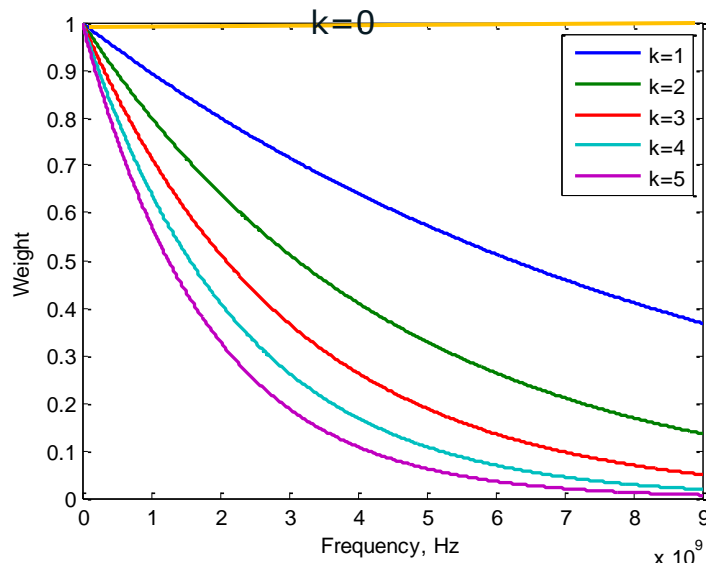
Trick about IL Decomposition

- ❑ Quality of insertion loss fit is VERY important – poor IL fit will result in a large (unreal) IMR
- ❑ Fitting is usually done from $f=0$ to the 2nd or 3rd harmonic
- ❑ Appropriate weighting function *must* be used in IL fit – more emphasis should be given from DC to Nyquist frequency
- ❑ Use $\text{IL_fit}(f)=\exp(a+b*\sqrt{f}+c*f+d*f^{1.5})$ as the standard fitting equation- the last term is to improve fitting accuracy
- ❑ Use $w=\exp(-k*f/\Delta f)$ as the standard weighting function for the least square fit, *where k is an adaptive factor*

Trick about IL Decomposition, cont.

- k may vary from 0 to 20 – increasing k shifts more emphasis to lower frequencies. In the extreme case of $k=0$, $w=1$ for all frequencies, which means no weight or equal weight for all frequencies!
- *Adaptively choose k such that IMR is a minimal. This allows us to get consistent/unique IL fit for each IL*

IL fit with $\min_k IMR$



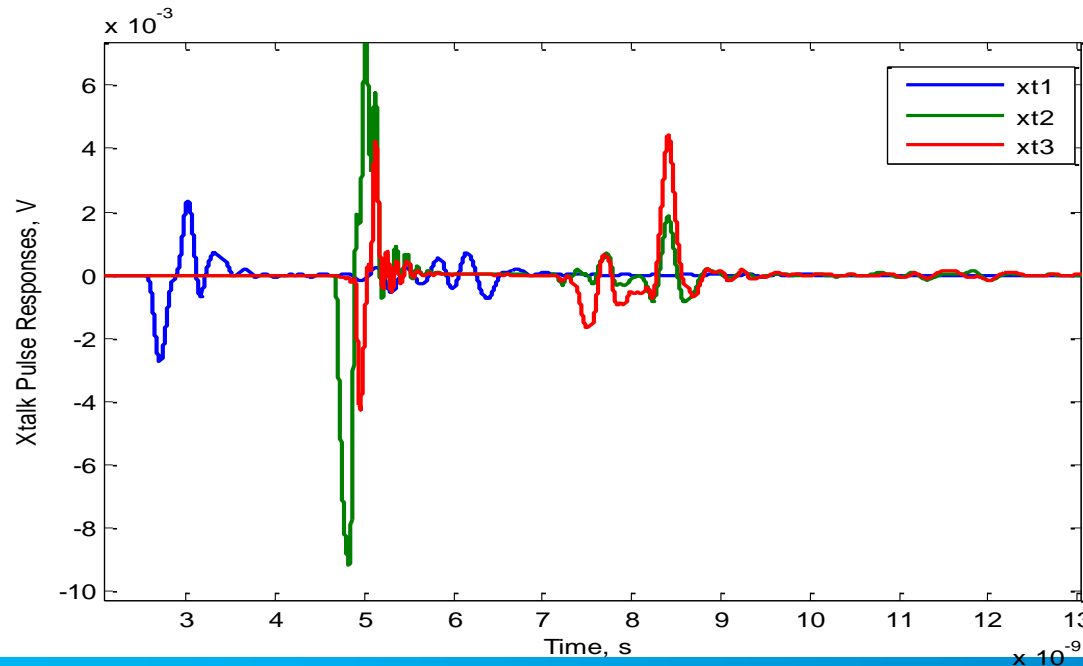
Integrated Crosstalk

- Integrated crosstalk noise is defined as the power sum of all crosstalk sources:

$$E_{xt} = \sum \int_{-\infty}^{+\infty} |xt_i(t)|^2 dt = \sum \int_{-\infty}^{+\infty} |XT_i(f)|^2 df$$

$$IXT = V_{sw} \sqrt{E_{xt} / E}$$

in V or mV, normalized
with a factor E

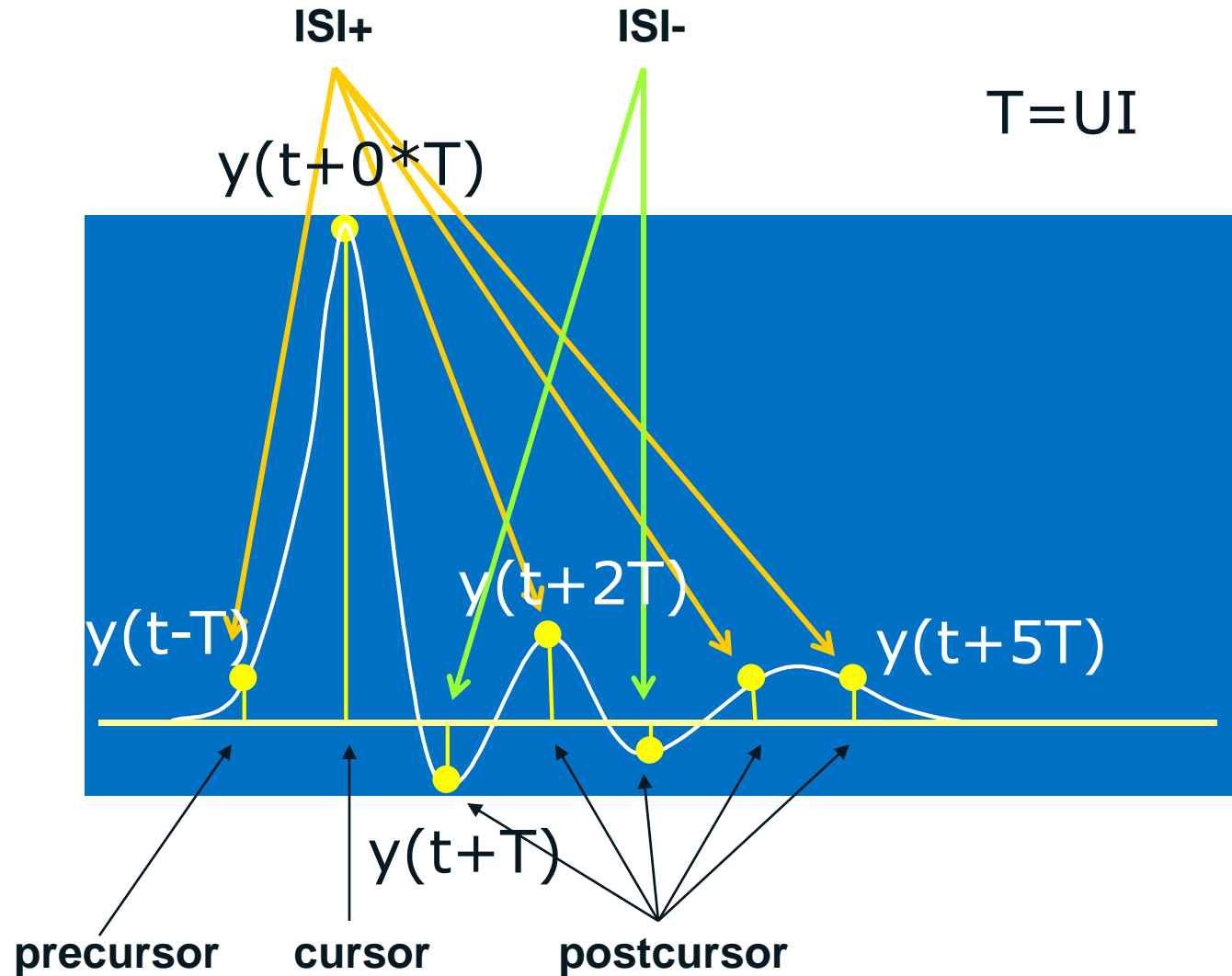


Channel Electrical Metrics Summary

- ❑ Three simple (scalar) parameters are used as the channel electrical metrics to account for three different impairments
 - IL fit at Nyquist frequency: ILfitatNq
 - Integrated multi-reflection: IMR
 - Integrated crosstalk: IXT
- ❑ Parseval's theorem establishes the frequency and time domain equivalency!
- ❑ An adaptive method is used for IL fit, which uniquely defines the IMR
 - The IL fit is done such that the IMR is minimized!

Channel Electrical Metrics and PDA

Start with pulse response



PDA Eye Equations

$$s_1(t) = \underset{\text{cursor}}{y(t)} + \underset{\substack{k=-\infty \\ k \neq 0}}{\sum} \underset{\text{ISI-}}{y(t-kT)} \Big|_{y(t-kT) < 0} + \underset{\substack{i=1 \\ n}}{\sum} \underset{k=-\infty}{\sum} \underset{\text{ith Crosstalk}}{y^i(t-kT-t_i)} \Big|_{y^i(t-kT-t_i) < 0}$$

Worst-case 1 eye edge

Sum all
crosstalk

ith Crosstalk

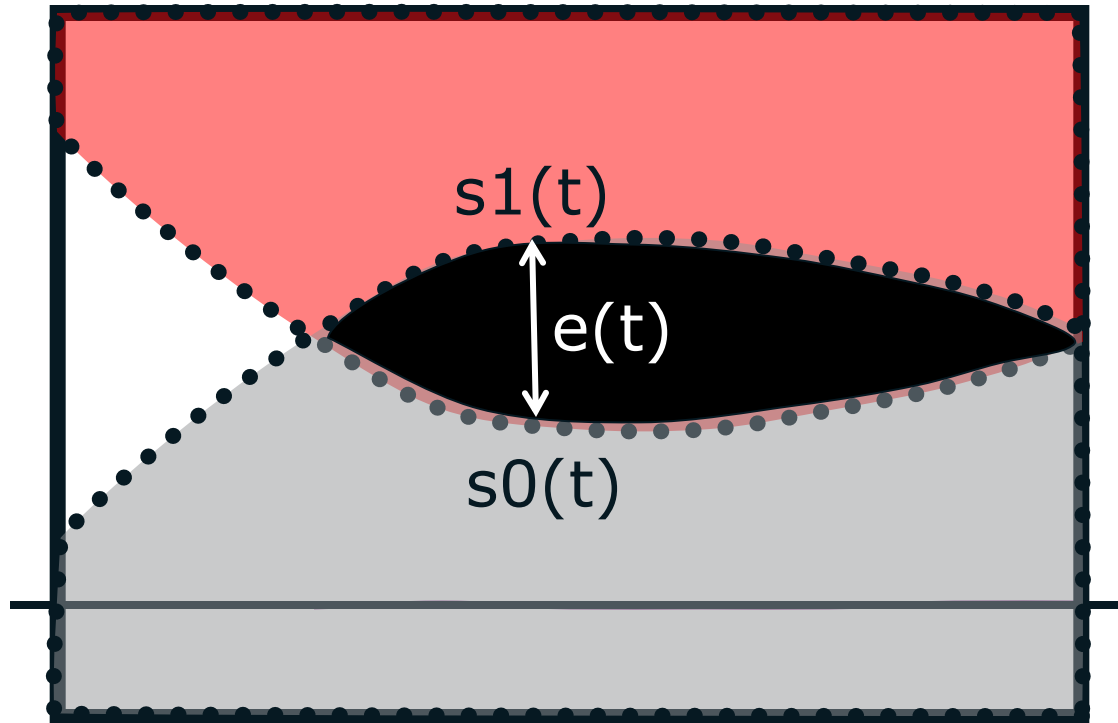
where t_i is the relative sampling point of each crosstalk pulse response.

$$s_0(t) = \underset{\substack{k=-\infty \\ k \neq 0}}{\sum} \underset{\text{ISI+}}{y(t-kT)} \Big|_{y(t-kT) > 0} + \underset{i=1}{\sum} \underset{k=-\infty}{\sum} y^i(t-kT-t_i) \Big|_{y^i(t-kT-t_i) > 0}.$$

Worst-case 0 eye edge

PDA Eye

$$e(t) = s_1(t) - s_0(t) = y(t) - \sum_{\substack{k=-\infty \\ k \neq 0}}^{\infty} |y(t - kT)| - \sum_{i=1}^n \sum_{k=-\infty}^{\infty} |y^i(t - kT - t_i)|$$



Re-arranging the PDA Equation

Decomposing ISI pulse into attenuation and multi-reflection

$$y(t) = y_{att}(t) + mr(t)$$

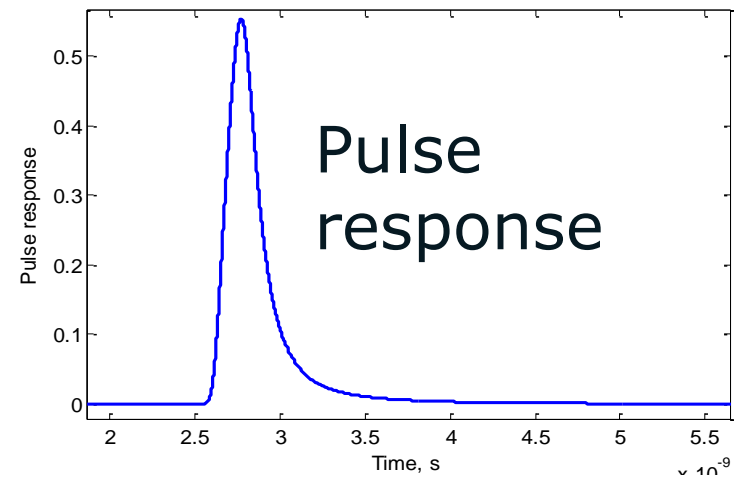
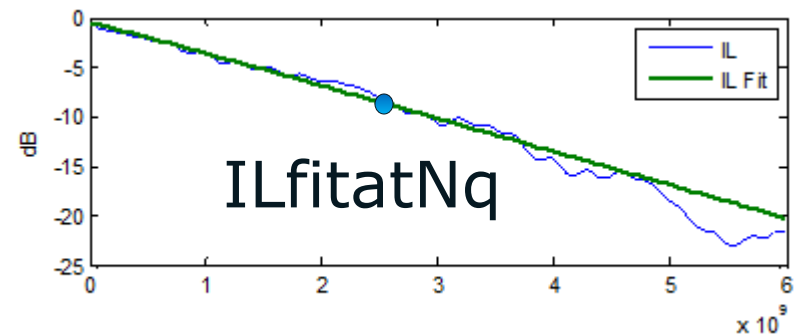
PDA eye becomes:

$$xt_i(t) = y^i(t)$$

$$e(t) = \underbrace{\left[y_{att}(t) - \sum_{\substack{k=-\infty \\ k \neq 0}}^{\infty} |y_{att}(t - kT)| \right]}_{\text{Attenuation}} - \underbrace{\left[\sum_{\substack{k=-\infty \\ k \neq 0}}^{\infty} |mr(t - kT)| - mr(t) \right]}_{\text{Multi-reflection}} - \underbrace{\left[\sum_{i=1}^n \sum_{k=-\infty}^{\infty} |xt_i(t - kT - t_i)| \right]}_{\text{Crosstalk}}$$

IL fit at Nyquist Frequency (ILfitatNq)

- ILfitatNq is measured at the IL fit, which is a smooth, monotonic curve (almost like straight line in dB at relatively high frequency)
- It is a reasonable representation of the "reflection-free" pulse response
- So ILfitatNq roughly catches the first term (attenuation)

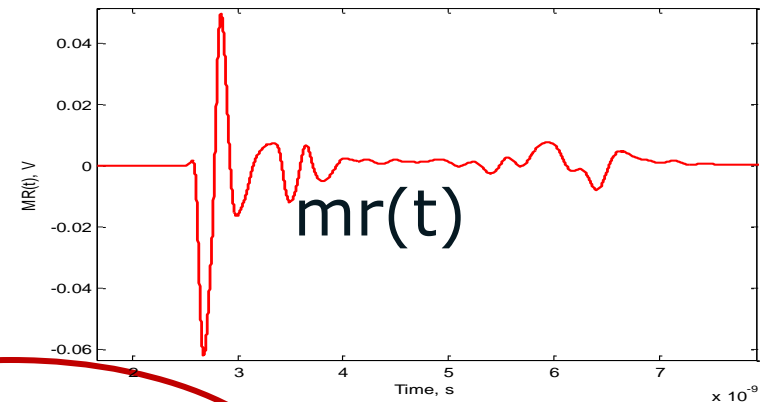


$$e(t) = \left[y_{att}(t) - \sum_{\substack{k=-\infty \\ k \neq 0}}^{\infty} |y_{att}(t - kT)| \right] - \left[\sum_{\substack{k=-\infty \\ k \neq 0}}^{\infty} |mr(t - kT)| - mr(t) \right] - \left[\sum_{i=1}^n \sum_{k=-\infty}^{\infty} |xt_i(t - kT - t_i)| \right]$$

Integrated Multi-reflection (IMR)

- IMR by definition is the integration of $mr(t)^2$. Alternatively, the integration of $|mr(t)|$ is probably equally valid
 - Integration of power $mr(t)^2$ is probably better because of the Parseval's theorem of time and frequency domain equivalency
- IMR is a figure of merit for multi-reflection impact
 - Summation and integration are directly correlated

$$IMR \propto \int_{-\infty}^{+\infty} |mr(t)|^2 dt = \int_{-\infty}^{+\infty} |MR(f)|^2 df$$



$$e(t) = \left[y_{att}(t) - \sum_{\substack{k=-\infty \\ k \neq 0}}^{\infty} |y_{att}(t - kT)| \right] - \left[\sum_{\substack{k=-\infty \\ k \neq 0}}^{\infty} |mr(t - kT)| - mr(t) \right] - \left[\sum_{i=1}^n \sum_{k=-\infty}^{\infty} |xt_i(t - kT - t_i)| \right]$$

Integrated Crosstalk (IXT)

- IXT by definition is integration and power sum of all crosstalk sources
- In PDA, the crosstalk term is the summation of all crosstalk sources at a certain fixed phase t_i
- In statistic analysis, crosstalks are often uncorrelated with random phase and power sum is probably more appropriate

$$IXT \propto \sum_{-\infty}^{+\infty} \int_{-\infty}^{+\infty} |xt_i(t)|^2 dt = \sum_{-\infty}^{+\infty} \int_{-\infty}^{+\infty} |XT_i(f)|^2 df$$

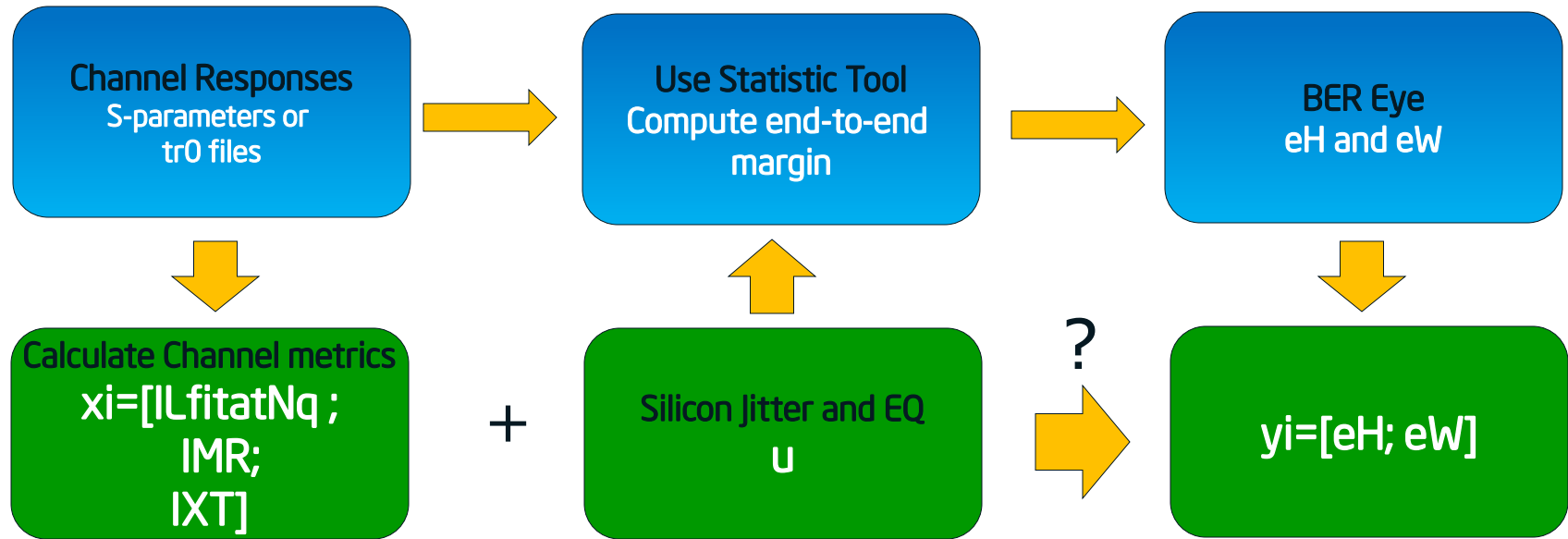
$$e(t) = \left[y_{att}(t) - \sum_{\substack{k=-\infty \\ k \neq 0}}^{\infty} |y_{att}(t - kT)| \right] - \left[\sum_{\substack{k=-\infty \\ k \neq 0}}^{\infty} |mr(t - kT)| - mr(t) \right] - \left[\sum_{i=1}^n \sum_{k=-\infty}^{\infty} |xt_i(t - kT - t_i)| \right]$$

Channel Metrics and PDA

- The development of the channel electrical metrics directly parallels the contribution to PDA eye by attenuation, multi-reflection and crosstalk.
- It is known that PDA eye is closely correlated with the channel end-to-end performance
- So it is reasonable to expect the proposed channel metrics to correlate with channel end-to-end performance also
- *The ultimate justification is to directly demonstrate the correlation between $IL_{fitatNq}$, IMR and IXT and the end-to-end BER eye margin*

Establishing End-to-End Correlation

Flow to Establish Correlation



Establish relationship

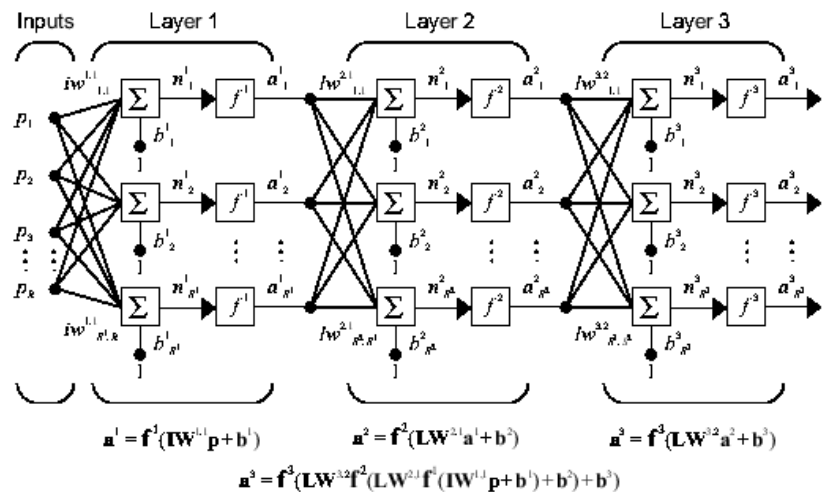
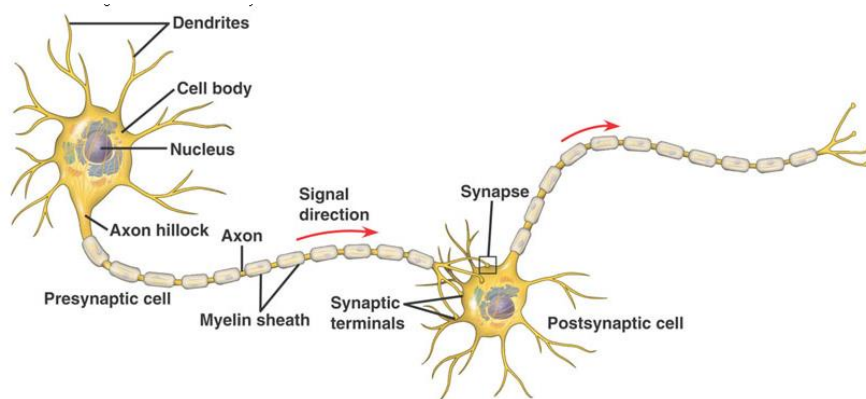
$$y = f(x; u)$$

y=End-to-end margin
f =Prediction function
X=Channel metrics
u=Silicon parameters

based on input $\{x_i; u\}$ and "observation" $\{y_i\}$, $i=1:n$

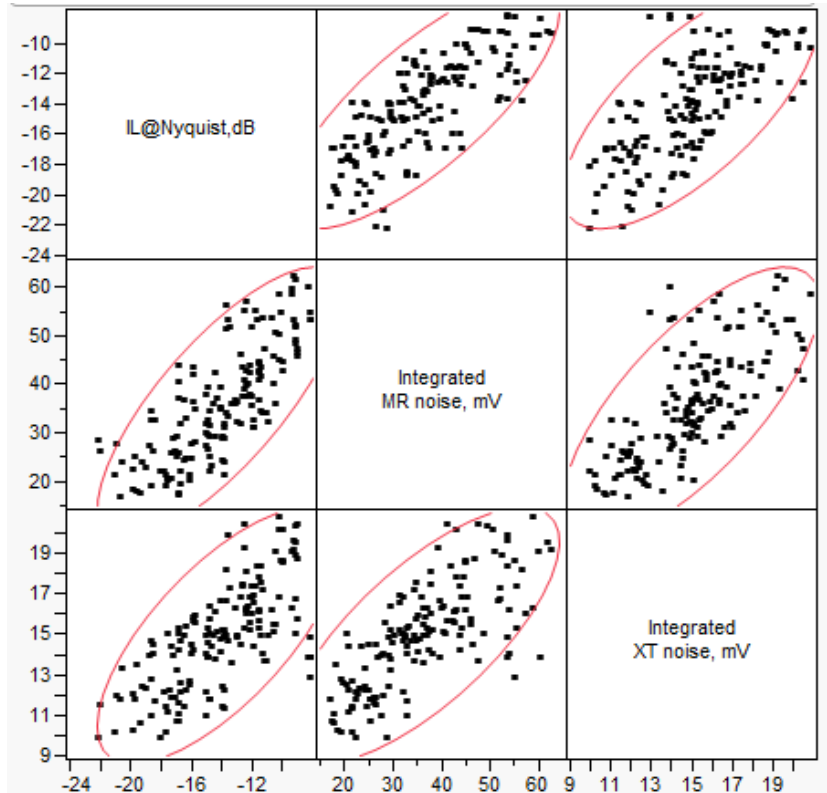
Neural Network Fit

- ❑ Neural network fitting is a powerful tool, capable of fitting almost any smooth function
- ❑ Neural network fitting can be used to establish the relationship between $\{x; u\}$ and $\{y\}$. (Note that u may be mostly fixed, hidden from customers)
- ❑ *The key to get good fit with neural network is appropriate space filling*

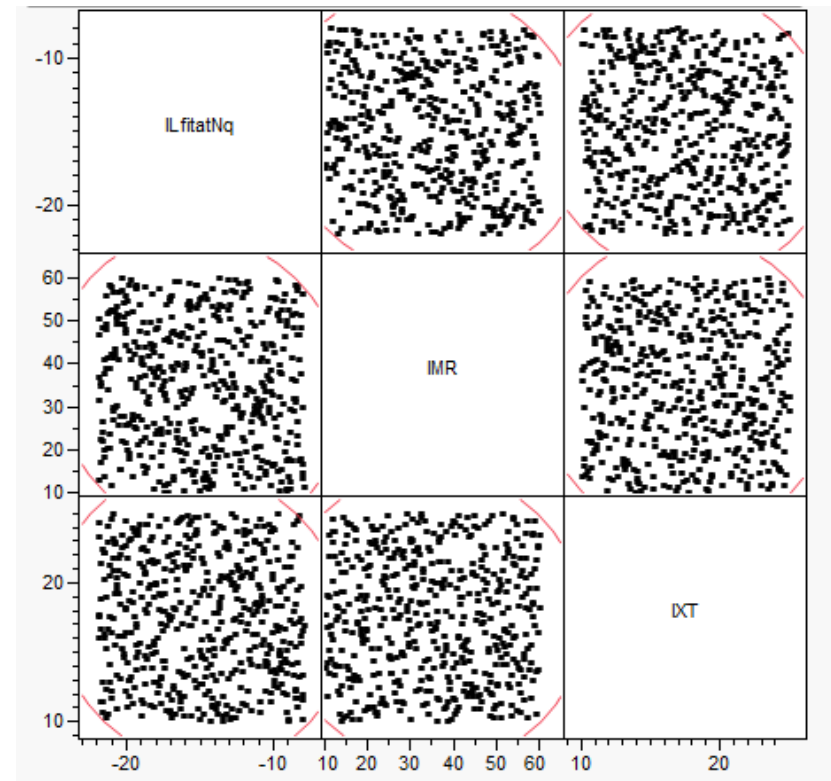


Space Filling

- The independent variables shall fill up the whole intended “design” space as uniformly as possible
- Not doing so will cause inaccurate fitting such as overfit

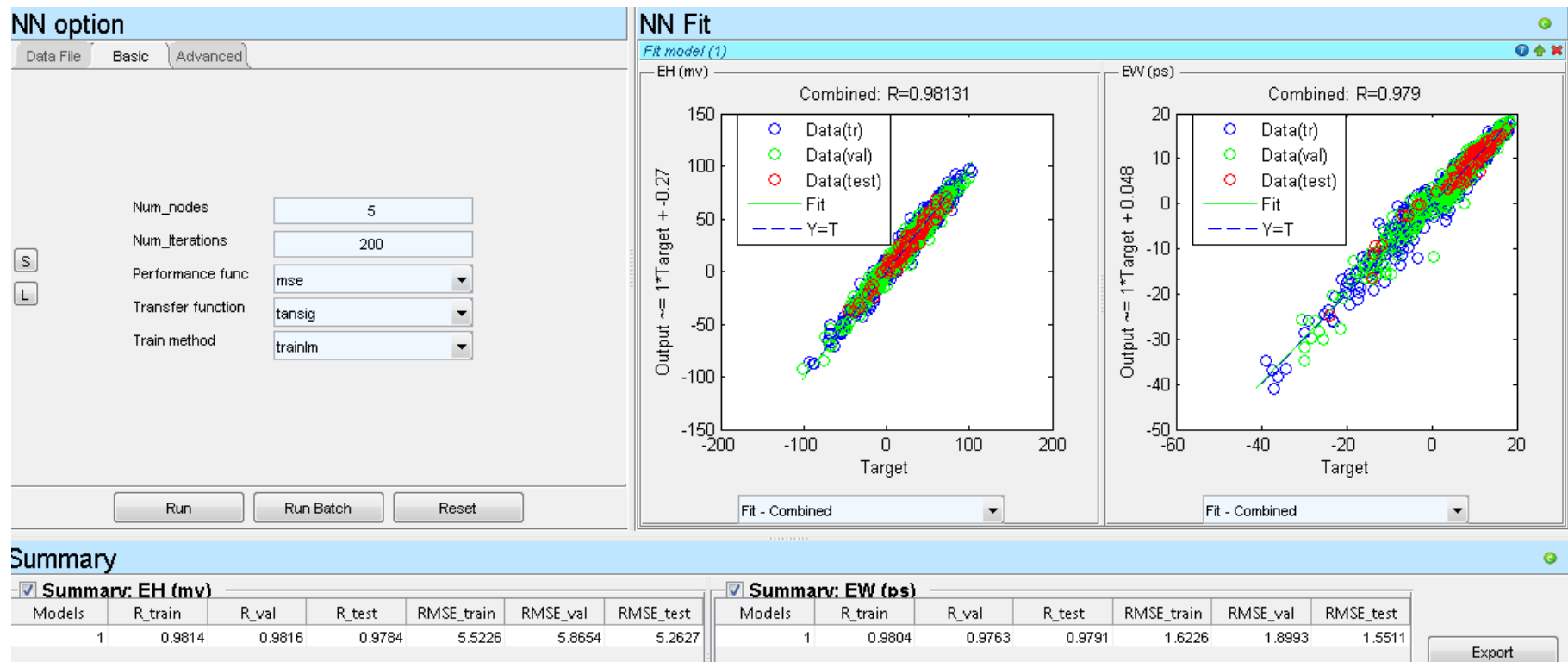


Not good



Desirable

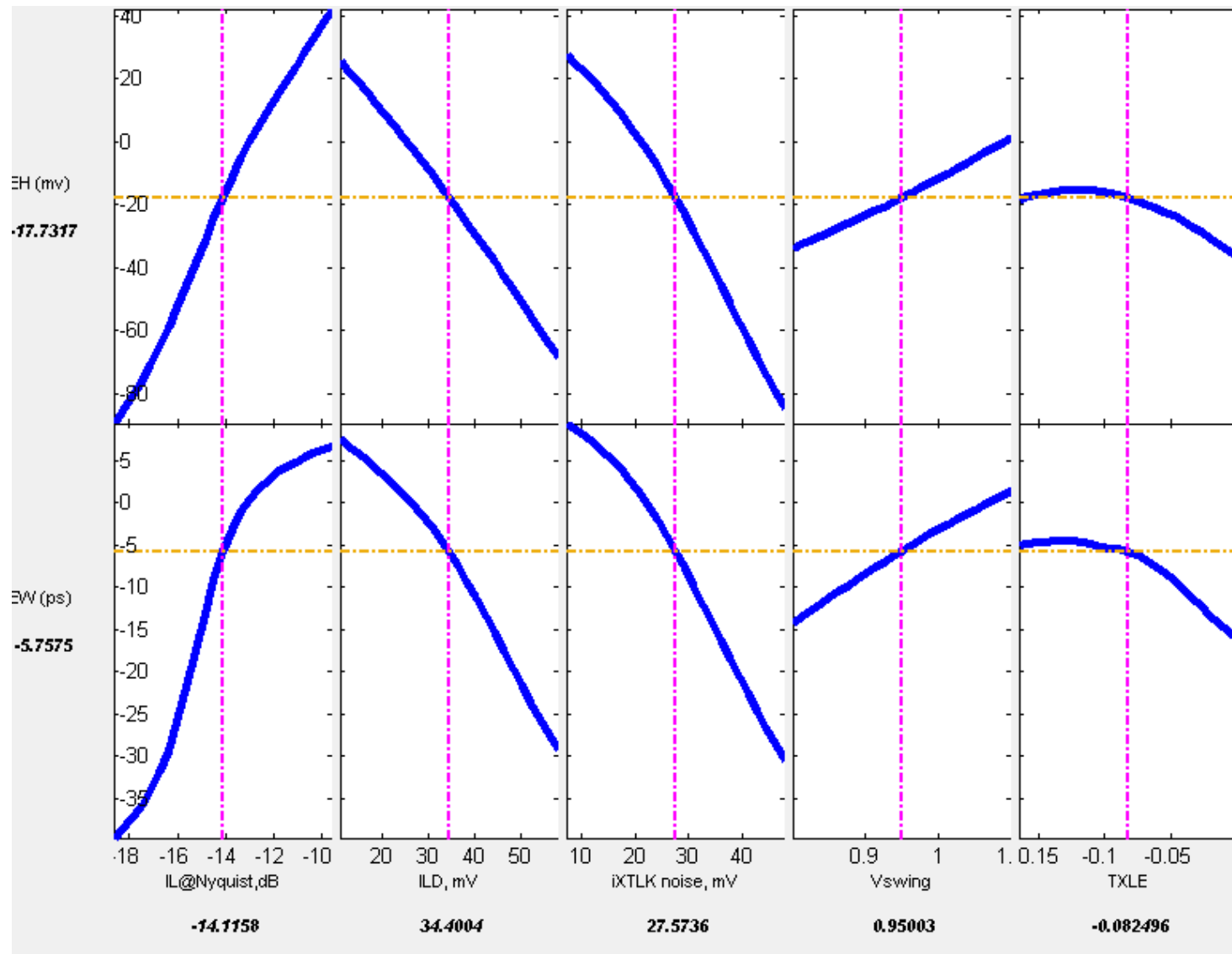
SATA Direct-Connect Rx Fit



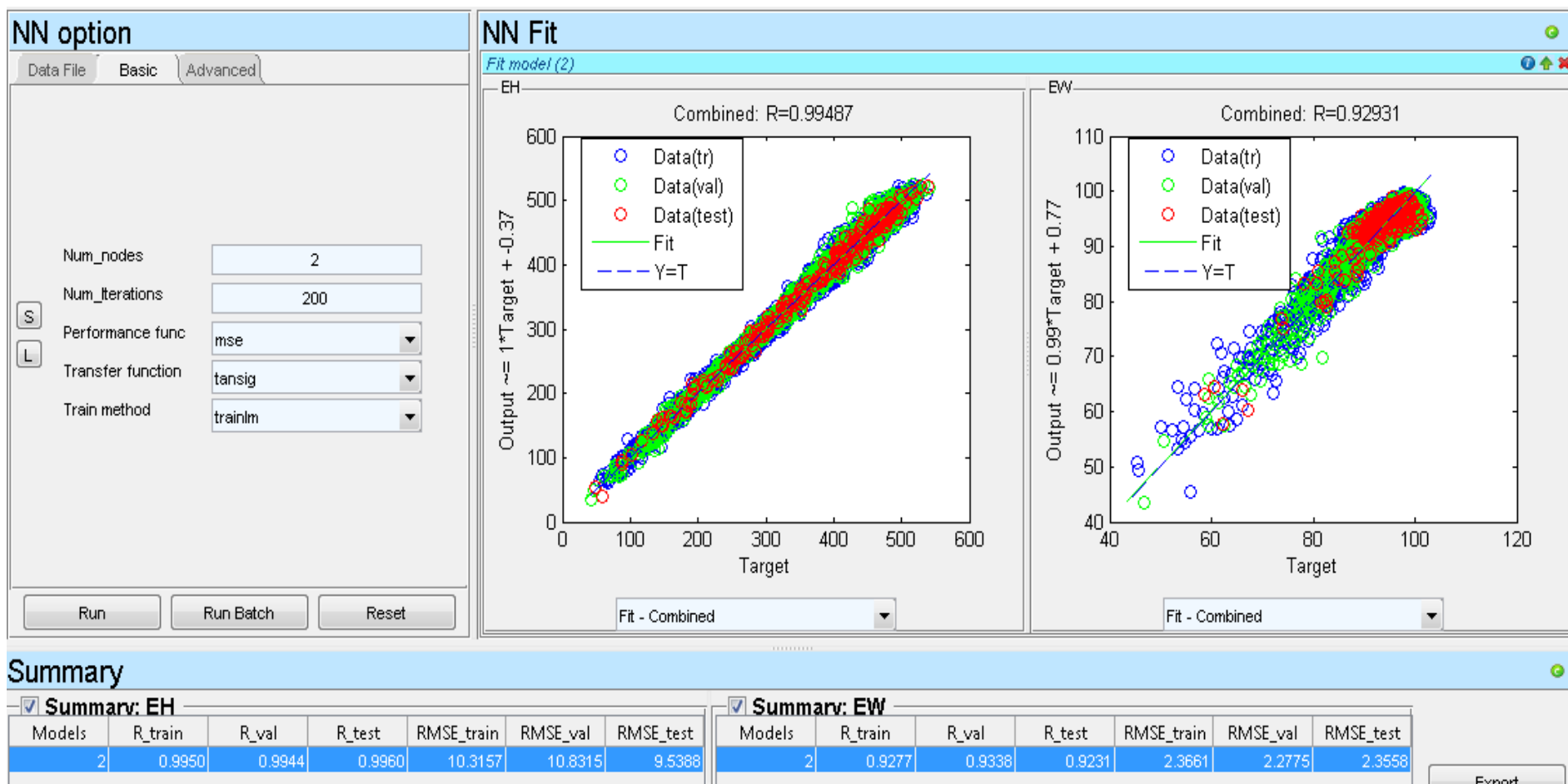
EH
R=0.981
RMSE=6 mv

EW
R=0.979
RMSE=2 ps

SATA Rx Fit Profiler

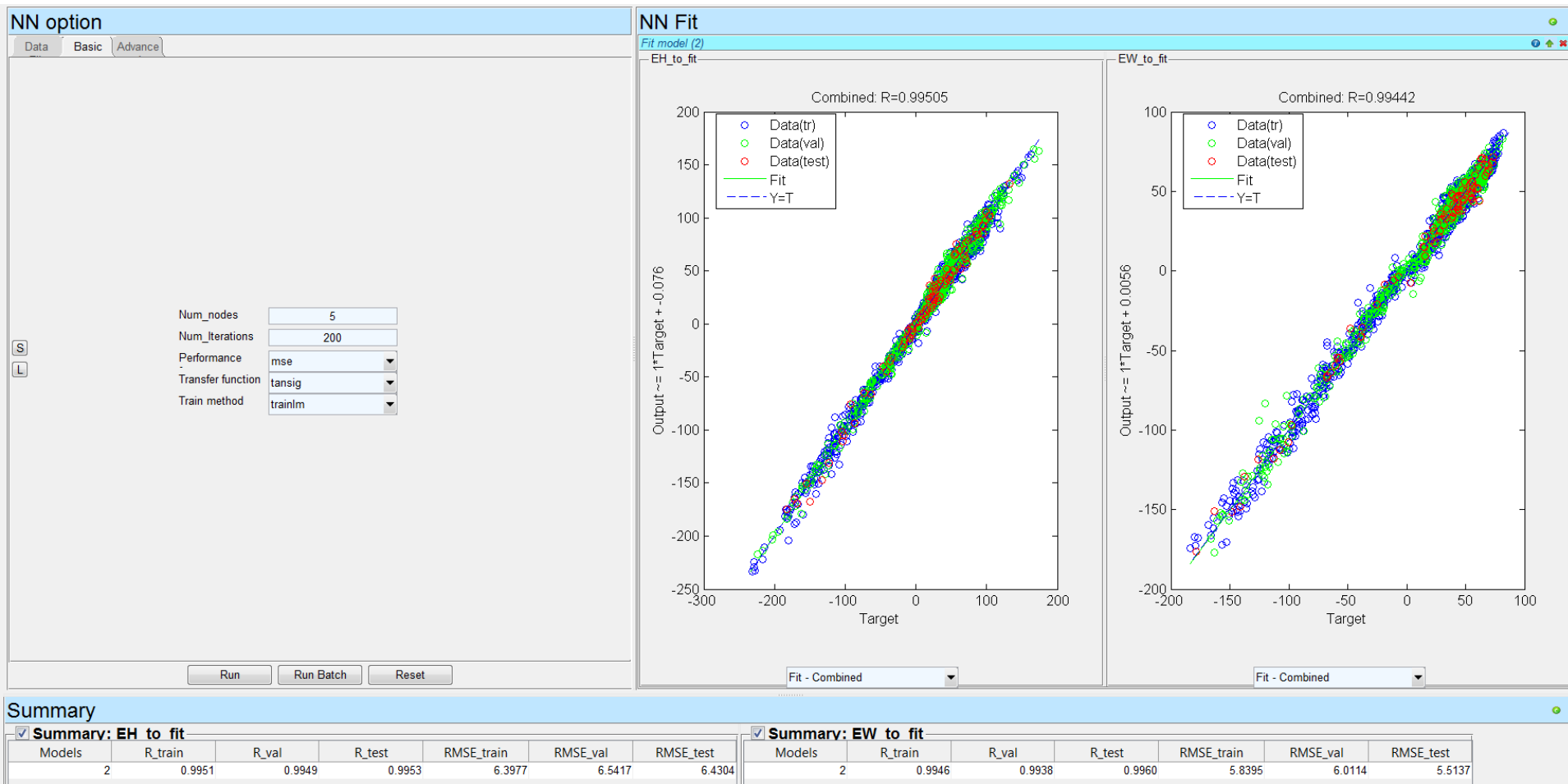


SATA Direct-Connect Tx Fit



Very good fit for EH and reasonable fit for EW

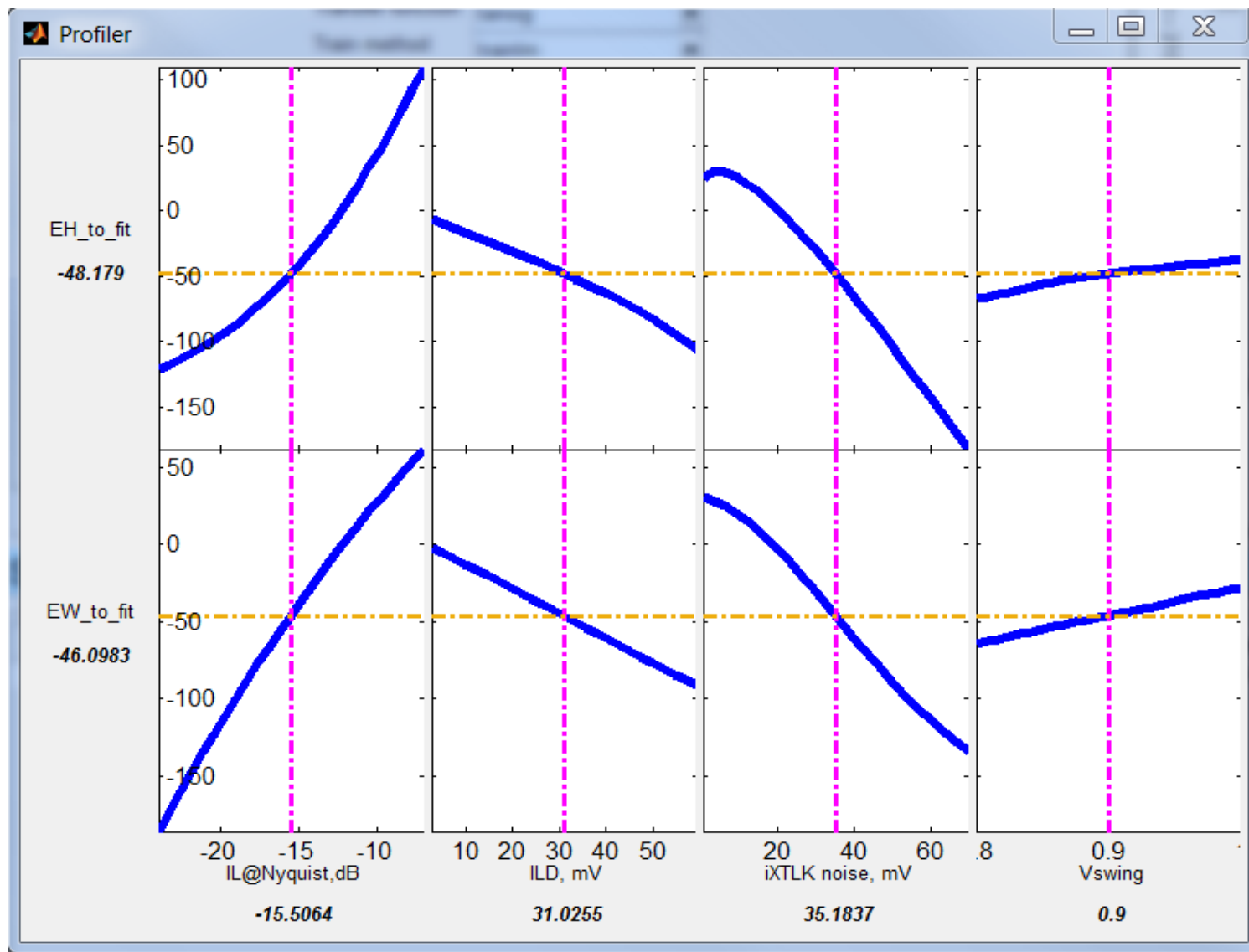
USB 3 Rx Fit Quality



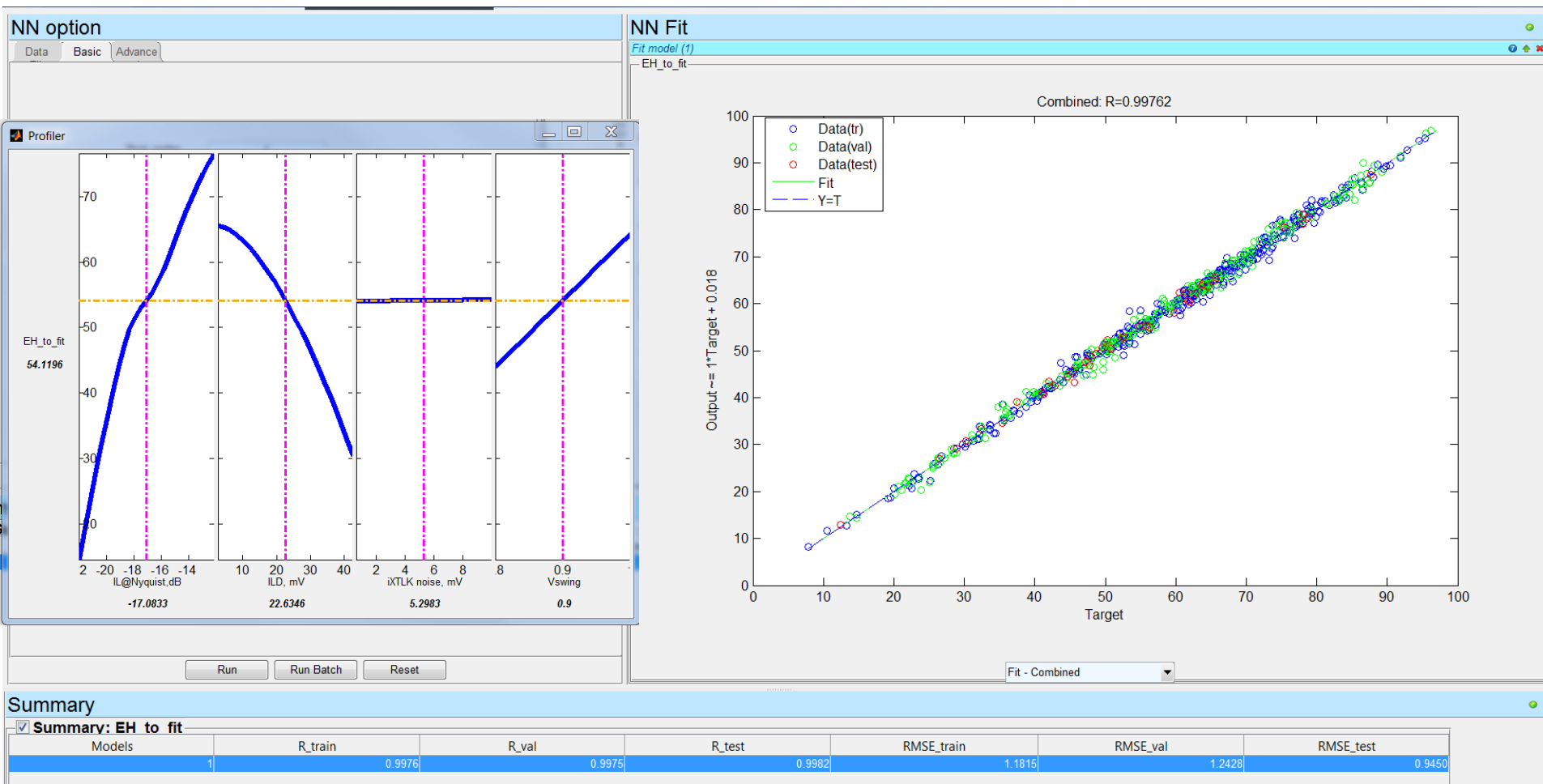
EH
R=0.995
RMSE=6 mv

EW
R=0.994
RMSE=6 ps

USB 3 Rx Fit Profiler

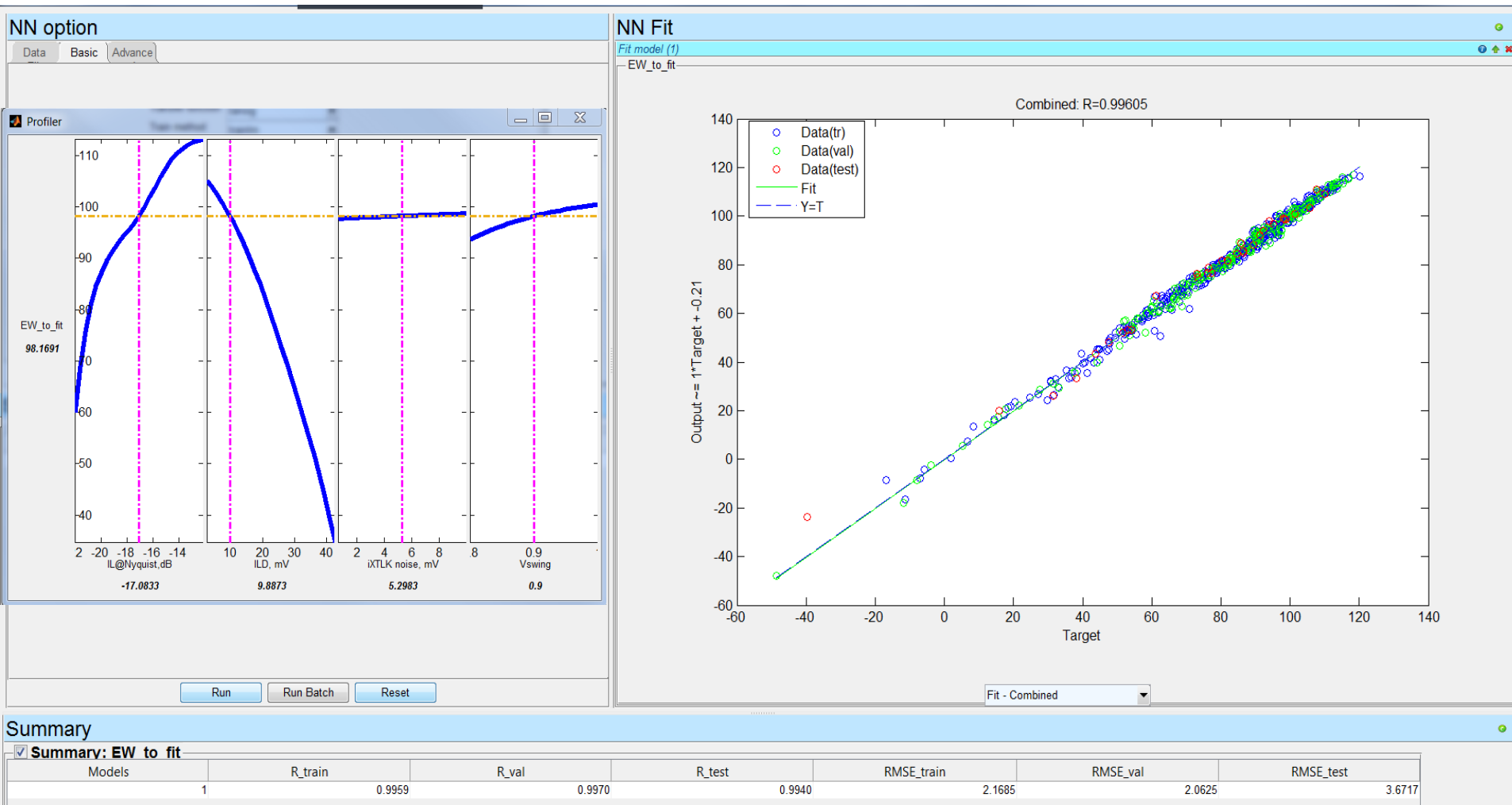


USB 3 Tx EH Fit



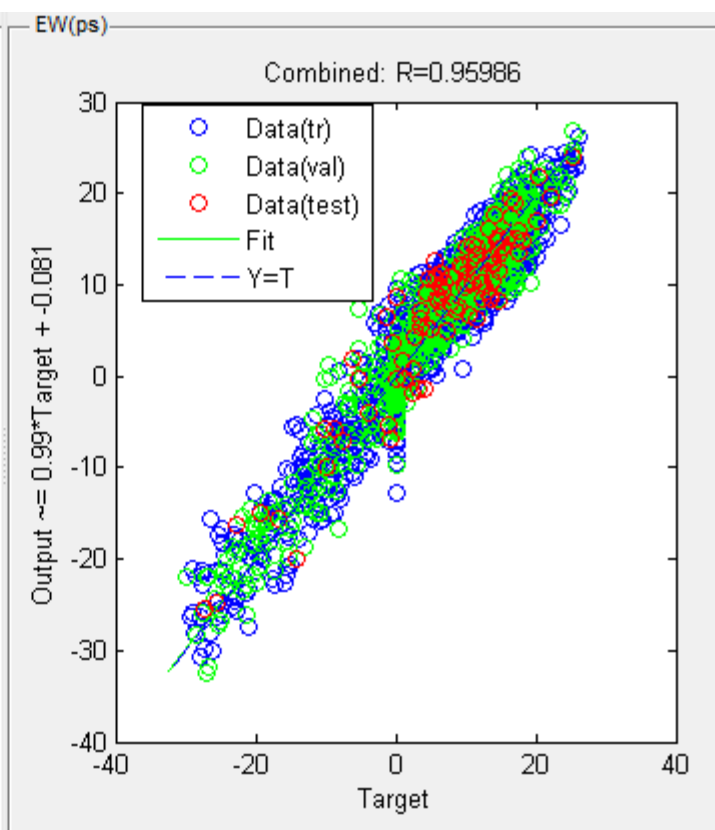
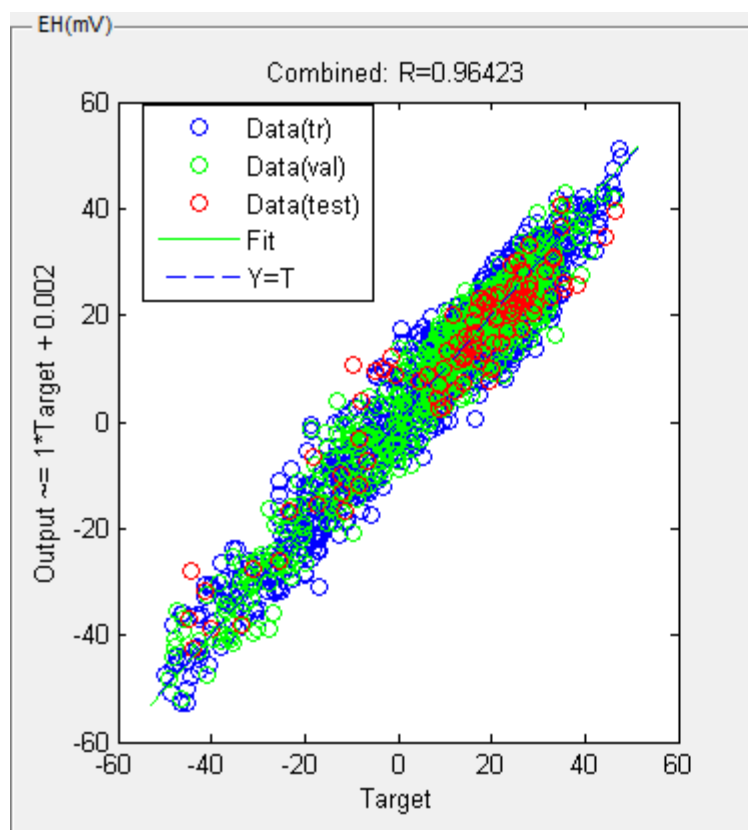
EH:R=0.998, RMSE=2 mV

USB 3 Tx EW Fit



EW: R=0.996, RMSE=3 ps

PCIe3 Example – LGA Rx: fitting quality



Summary: EH(mV)

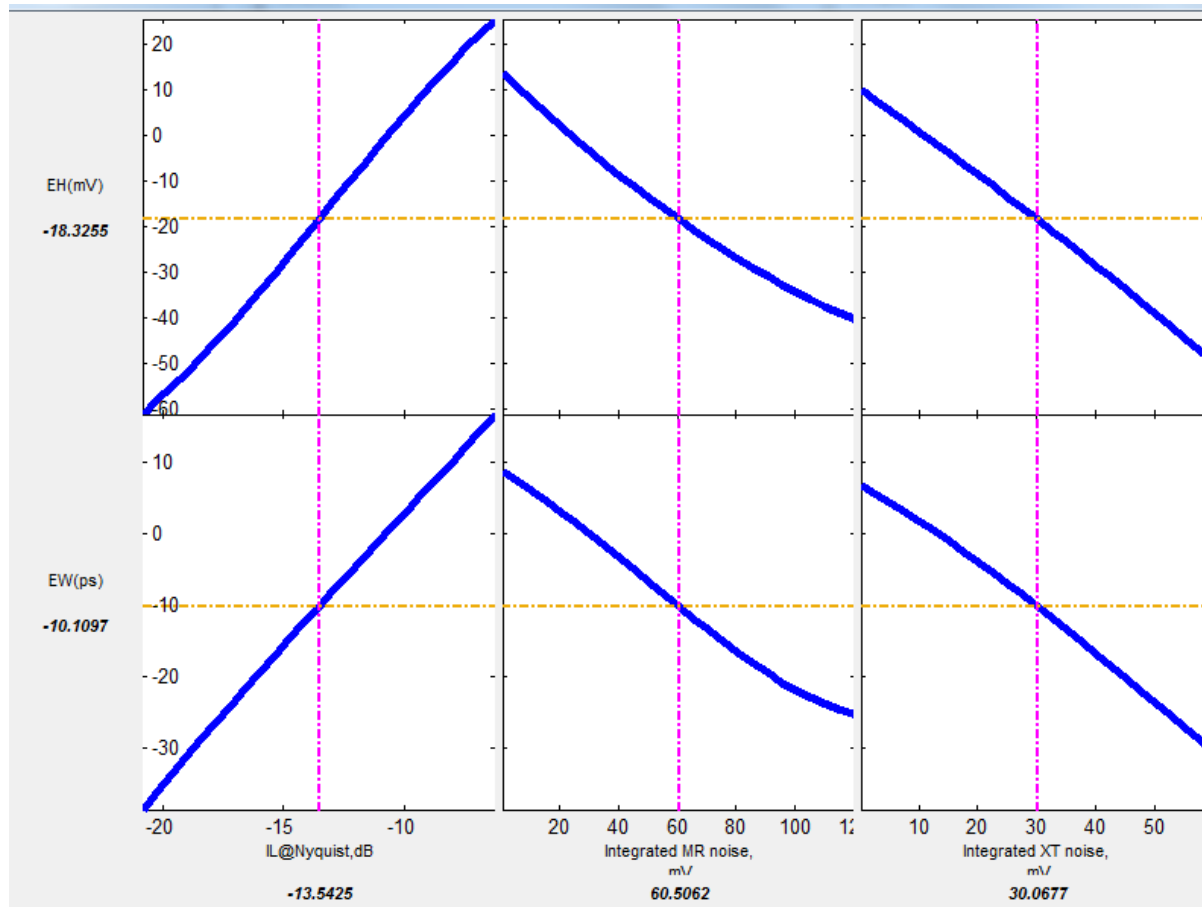
Models	R_train	R_val	R_test	RMSE_train	RMSE_val	RMSE_test
1	0.9647	0.9653	0.9544	5.0887	5.2277	6.2706

Summary: EW(ps)

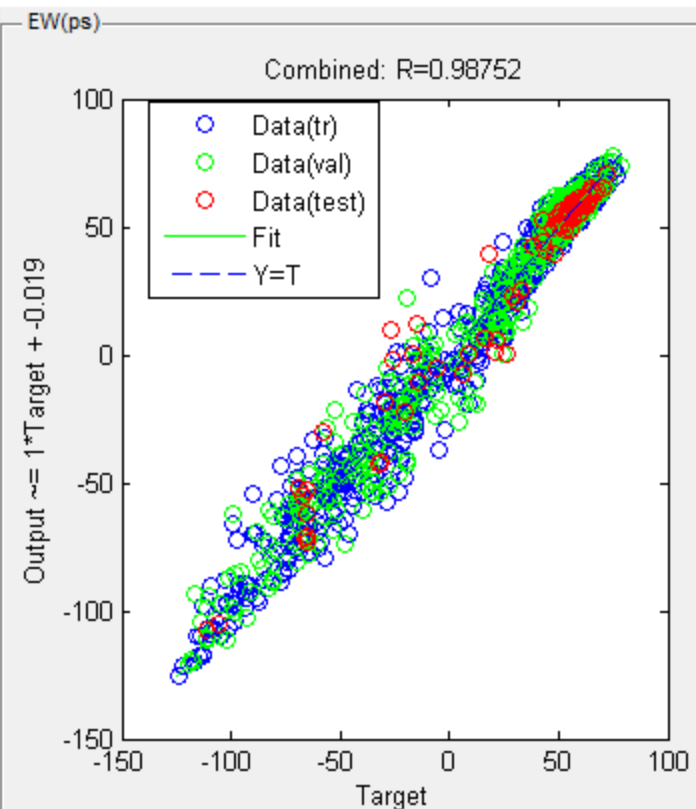
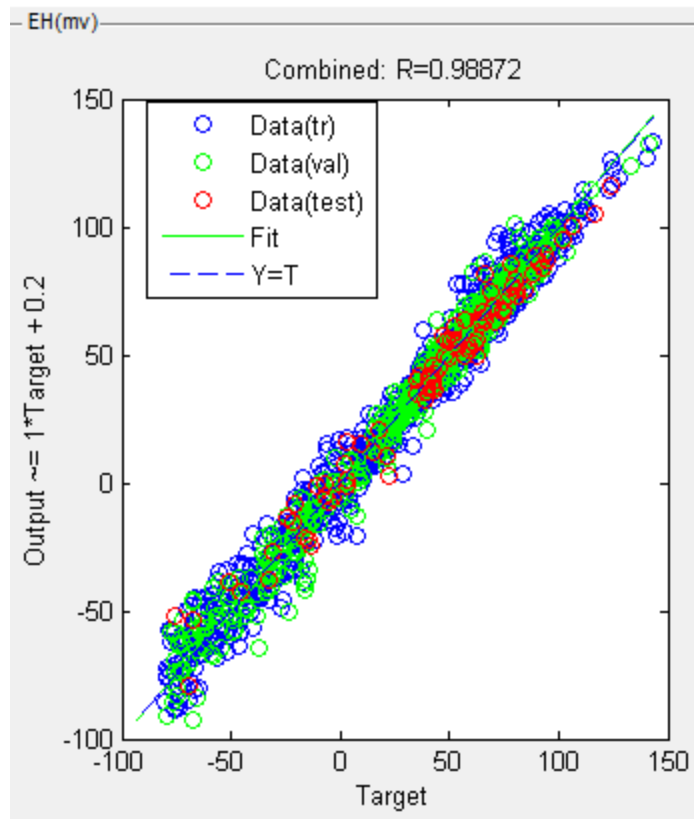
Models	R_train	R_val	R_test	RMSE_train	RMSE_val	RMSE_test
1	0.9598	0.9625	0.9422	3.0498	3.1199	3.3875

PCIe3 Example – LGA Rx: Profiler

Fitting with ILfit@Nquist, IMR, IXtlk



PCIe3 Example – LGA Tx: fitting quality



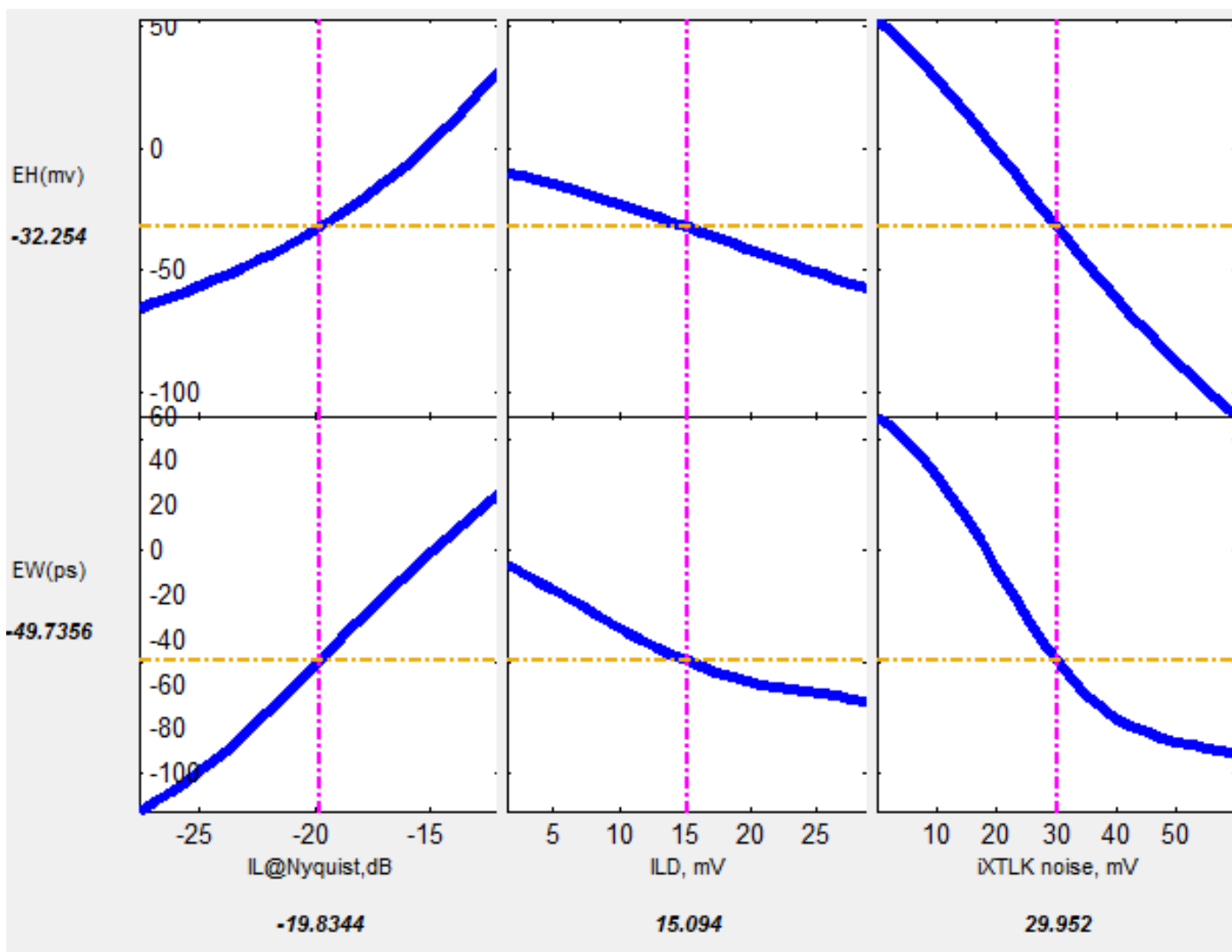
Summary: EH(mv)

Models	R_train	R_val	R_test	RMSE_train	RMSE_val	RMSE_test
1	0.9888	0.9889	0.9869	6.8067	6.7239	7.2564

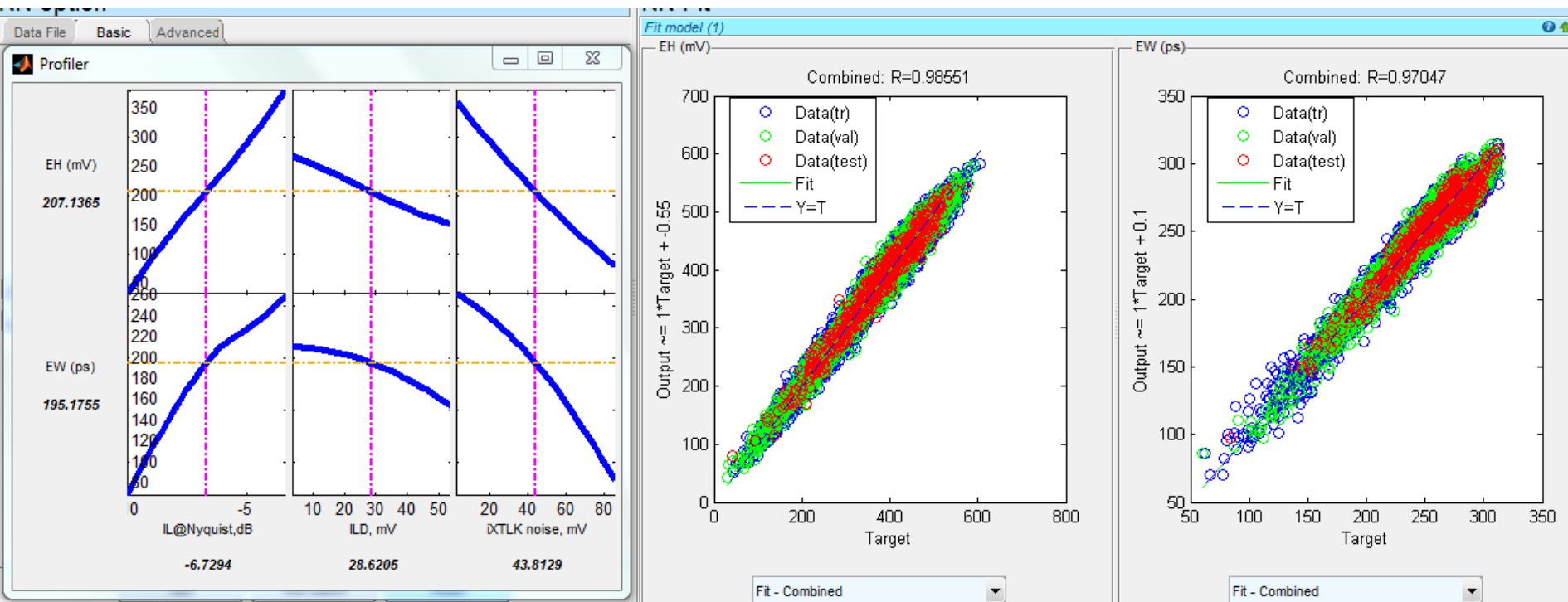
Summary: EW(ps)

Models	R_train	R_val	R_test	RMSE_train	RMSE_val	RMSE_test
1	0.9887	0.9864	0.9795	6.9995	8.2069	9.1955

PCIe3 Example – LGA Tx: profiler



DisplayPort HBR1 Fit



Summary

Summary: EH (mV)

Models	R_train	R_val	R_test	RMSE_train	RMSE_val	RMSE_test
1	0.9851	0.9867	0.9830	15.9337	15.6010	16.2196

Summary: EW (ps)

Models	R_train	R_val	R_test	RMSE_train	RMSE_val	RMSE_test
1	0.9710	0.9693	0.9702	8.2380	8.2616	8.0083

Summary

Summary

- ❑ Three simple (scalar) parameters are used as the channel electrical metrics to account for three different impairments
 - IL fit at Nyquist frequency: ILfitatNq
 - Integrated multi-reflection: IMR
 - Integrated crosstalk: IXT

- ❑ Parseval's theorem establishes the frequency and time domain equivalency!
 - It doesn't matter in time domain or freq domain!

- ❑ An adaptive method is used for IL fit, which uniquely defines the IMR
 - The IL fit is done such that the IMR is minimized!

Summary, cont.

- Neural network fitting together with space filling is used to fit the channel electrical metrics against the end-to-end eye margin to establish the (passive) channel electrical spec
- The proposed (passive) channel electrical metrics, ILfitatNq, IMR and IXT, are closely correlated with the channel end2end BER eye margins
 - *We have tested this for virtually all differential interfaces and haven't found any exception so far*
- The fitting quality is in general good, usually better than the typical fitting in DOE.

